INSTRUCTION MANUAL

SERIAL DRUM SYSTEM TYPE RM08



DIGITAL EQUIPMENT CORPORATION . MAYNARD, MASSACHUSETTS

SERIAL DRUM SYSTEM TYPE RM08 INSTRUCTION MANUAL

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CHAPTER I

This manual describes the operation of and provides maintenance information on the Digital Equipment Corporation Type RM08 Serial Drum System.

1.1 PURPOSE

The Type RM08 Serial Drum System is used in conjunction with the Programmed Data Processor-8 (PDP-8) as an auxiliary data storage device. Information in the PDP-8 can be stored in the RM08 drum and retrieved in sectors of 16 computer words. Sectors are automatically transferred between the PDP-8 core memory and the drum after program initialization. Transfer of each word is interleaved with the running computer program under control of the PDP-8 data break facilities. A word is transferred in parallel (12 bits at a time) and is read from or written onto the surface of the rotating drum in serial fashion (one bit at a time).

Words within the drum system consist of 12 information bits and a parity bit. Parity bits are generated internally when writing, and are checked when reading. The drum system has 64 tracks – each track holds 64 sectors of 16 13-bit words. The storage capability can be expanded to 256 tracks (262,144 words).

1.2 PHYSICAL DESCRIPTION

The Type RM08 Serial Drum System is contained in a DEC computer cabinet 23-1/2 in. wide, 27-1/16 in. deep, and 69-1/8 in. high. All indicators are located on a panel at the front of the machine.

A coordinate system is used to locate racks, modules, cable connectors and terminals. Each 5–1/4 in. position on the front of the cabinet is assigned a capital letter beginning with A at the top, as indicated in Figure 1–1. Modules are numbered from 1 through 25 from left to right in a rack, as viewed from the wiring side (front). Connectors are numbered from 1 through 6 from left to right, as viewed from the front of the machine. Blank-module and connector locations are not numbered, and terminals on a module connector are designated by capital letters from top to bottom. For example, D09E is the fourth location from the top (D), the ninth module from the left (09), and the fifth terminal from the top of the module. Engineering drawing D-RM08–0–6 (Chapter 7) shows the module types used in racks 1C, 1D, and 1E.

Table 1-1 lists the specifications for the Type RM08 Serial Drum System.

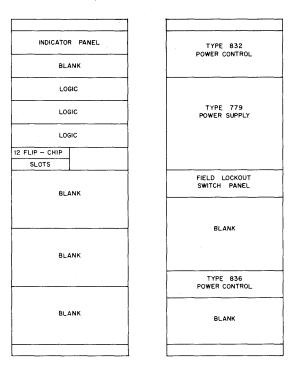


Figure 1-1 Component Location-RM08

Table 1-1 Specifications

69-1/8 in. high

Dimensions:

23-1/2 in. wide 27-1/16 in. deep

Service Clearances:

8-3/4 in. front 14-7/8 in. rear

Weight:

500 lb.

Power Requirements:

115V, 60 c/s, single phase

240V, 50 c/s, single phase

8A starting current 5A running current 4A starting current 2.5A running current

Power Control Point:

Local or remote (computer)

Signal Cables:

11 10-ft, 9-conductor coaxial cables with W021 connectors

Table 1–1 (continued) Specifications

Ambient Temperature:

60°F to 100°F

Initial Starting Delay:

5 min.

Drum Motor:

115V or 245V, single phase, 2 pole, induction, capacitor start and run

Write Current:

120 mA

Drum Speed:

3600 rpm (60 c/s) 3000 rpm (50 c/s)

Word Transfer Time:

15.6 µs (3600 rpm)

19.5 μs (3000 rpm)

Sector Transfer Cycle:

250 µs (3600 rpm)

313 µs (3000 rpm)

Access Time:

8.65 ms (17.3 ms max at 3600 rpm)

10.3 ms (20.5 ms max at 3000 rpm)

1.3 ABBREVIATIONS

The following abbreviations are used in text throughout this manual and on the engineering drawings of Chapter 7.

Abbreviation	Definition	Abbreviation	Definition
AC ACT	Accumulator in computer Active	DDC	Drum data channel in serial drum
AMP	Amplifier	DE	Data error
COND	Condition	DF and DFB	Drum final buffer in serial drum
CLR	Clear	DS	Device selector in serial drum
DCL	Drum core location counter in serial drum	DSA	Drum sector address
DCT	Drum control element in serial drum	DTA INT	Drum track address Interrupt control in computer

Abbreviation	Definition	Abbreviation	Definition
IOT	Input/Output transfer	PE	Parity error
MA and MAR	Memory address register in	PG	Pulse generator
	computer	RQ	Request flip-flop
MB	Memory buffer register in computer	R PARITY	Read/write parity flip-flop in serial drum
PA	Pulse amplifier	SC	Sector counter in serial drum
PAR	Parity	SA	Sector address
DSB CONTROL	Drum serial buffer control (– 3V source)	TRA	Transfer

1.4 ASSOCIATED PUBLICATIONS

The following documents are pertinent to the RM08 Serial Drum Systems.

PDP-8 Users Handbook, PDP-8 Maintenance Manual, Systems Modules Catalog, C-100 FLIP-CHIP Modules Catalog, C-105

CHAPTER 2 PRINCIPLES OF OPERATION

2.1 FUNCTIONAL DESCRIPTION

The major functional areas of the Type RM08 Serial Drum System are illustrated in Figure 2-1 and are described in the following paragraphs. Detailed engineering diagrams for the serial drum logic are contained in Chapter 7. The references in text are to the engineering drawing numbers. Complete information transfer flow is illustrated in Dwg. No. D-RM08-0-23.

2.1.1 Device Selector

During the execution of an IOT instruction, the device selector receives MB bits 3 through 8 and the IOP1, IOP2, and IOP4 pulses from the computer. The internal structure of the device selector, which consists of three Type 4605 modules, permits it to generate the IOT pulses which control the drum circuits during an IOT instruction. The device selector is shown in the lower right-hand corner of Dwg. No. D-RM08-0-4.

2.1.2 Drum Core Location Counter (DCL)

The drum core location counter (Dwg. No. D-RM08-0-5) is a 15-bit register which addresses the next core location to or from which the next word is to be transferred. Prior to transfer of the initial word in a block, the address of the first word is set into the DCL under program control from the computer accumulator. As each word is transferred, the DCL is incremented by one.

2.1.3 Drum Track (DTA) and Sector Address (DSA) Registers

The DTA and DSA registers (Dwg. No. D-RM08-0-5) comprise a 14-bit register (8 tracks and 6 sectors) which addresses the drum track and sector which is currently transferring data. Upon completion of a successful last sector transfer (error flag is 0), these registers are incremented by one.

2.1.4 Drum Field and Sector Number Registers

The drum field register is a 2-bit register which holds the drum field. The sector number register is a 6-bit register specifying the number of sectors to be transferred. The contents of these registers can only be changed by an IOT. The drum field register is a 2-bit register which specifies one of four drum fields (64K wordsper field) to which the data will be transferred. These registers are shown in (Dwg. No. D-RM08-0-3).

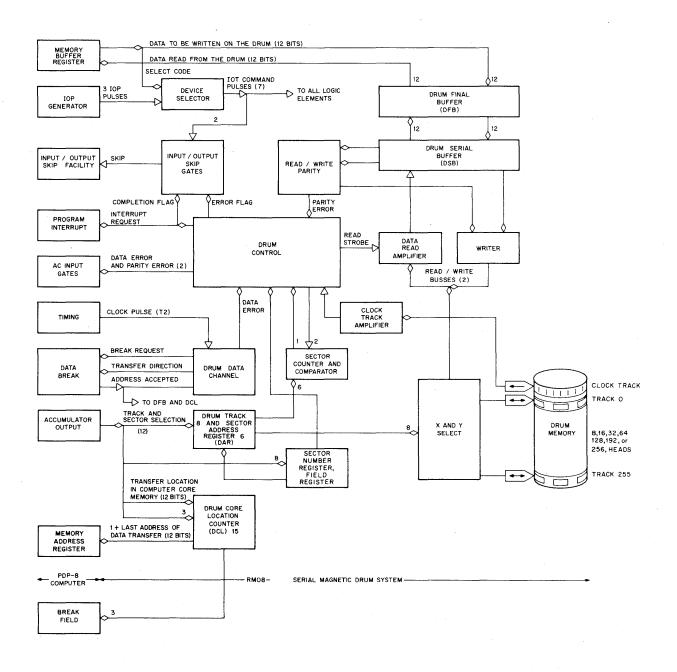


Figure 2-1 Type RM08 Functional Diagram

2.1.5 Sector Number Counter

The sector number counter (Dwg. No. D-RM08-0-21) is a 7-bit counter which contains the 2s complement of the sector number register. The number of sectors transferred is counted, and any overflow produces a flag interrupt condition. The sector counter is a 6-bit counter which is incremented automatically after each sector of clock information.

2.1.6 Drum Final Buffer (DFB)

The drum final buffer (Dwg. No. E-RM08-0-3) is a 12-bit register under control of the data break facility which is a buffer between the memory buffer register and the drum serial buffer. During write-in, the DFB holds the next word to be written. During read-out, the DFB stores the word read from the drum until it is transferred to the PDP-8.

2.1.7 Drum Serial Buffer (DSB)

The drum serial buffer (Dwg. No. E-RM08-0-3) is a 14-bit register which contains a data word and two control bits. This register serves as a serial-to-parallel converter during read-out, and as a parallel-to-serial converter during write-in. Information is read from the drum into the DSB in serial fashion and is transferred into the DFB in parallel. During write-in, a word is transferred in parallel from the DFB to the DSB and written serially around the drum.

2.1.8 Drum Head Selection

Selection of a drum head is performed in the drum X and Y select circuits (Dwg. No. E-RM08-0-2) and in the diode matrix within the drum housing. The 16 FIELD LOCKOUT switches, when closed, inhibit the X0 and X1 selection modules to prevent writing on certain tracks which may contain data the programmer wishes to preserve. Each switch inhibits writing on four tracks (4096₁₀ words).

2.1.9 Drum Control

The basic timing pulses for the machine are generated in the DCT from pulses received from the clock track amplifier. The DCT also contains a 4-stage device consisting of four negative diode gates. Each state of this device corresponds with and initiates one of the machine control states: idle (IDLE), transfer (TRA), active (ACT), or transfer done (COMP FLAG). This logic is shown on Dwg. No. D-RM08-0-4).

2.1.10 Read-Write Parity

As each bit of a word is written on the drum surface, the R PARITY flip-flop counts the number of binary 1's and produces a 13th bit to provide odd parity. When data is read from the drum, this flip-flop again counts the 1's and sets the parity error (PE) flip-flop if an even number is detected in any word. The condition of the PE flip-flop is indicated in the DCT as one of the two possible causes of an error condition. These circuits are shown in area C4 of Dwg. No. E-RM08-0-3.

2.2 RECORDING AND PLAYBACK TECHNIQUE

The recording and playback technique employed in the Type RM08 Serial Drum System is NRZ (non-return-to-zero) phase modulation. This technique records binary 1's and 0's by controlling the direction of flux change on the drum surface. For example, a flux change in one direction represents a 1, and a flux change in the opposite direction represents a 0.

To clarify this point, consider the timing diagram Figure 2-2 and the simplified logic diagram Figure 2-3. As shown on these drawings, a positive voltage swing (identified by the arrow) from the write flip-flop produces a flux change to write a 1, and a negative voltage swing produces a flux change to write a 0. The read/write circuits are synchronized so that recording occurs on the phase A time pulse. The write flip-flop must be in a state so that the phase A pulse can complement the flip-flop to write the specified bit. The phase B pulse shifts the bit to be written into the last bit of the data register, the DSB0 flip-flop. The delayed phase B pulse senses the DSB0 bit to put the write flip-flop in the proper state so that the next phase A pulse complements the write flip-flop to write the bit specified by DSB0.

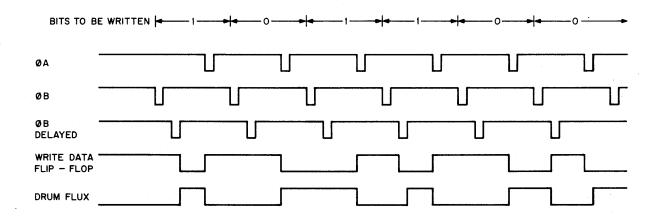


Figure 2-2 Simplified Timing - NRZ Writing

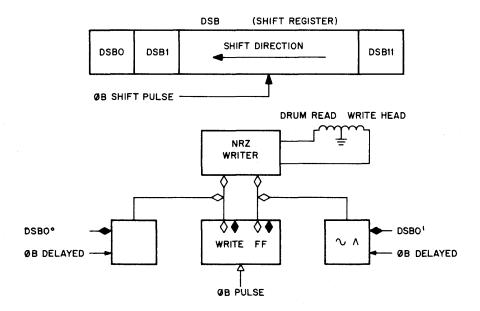


Figure 2-3 Simplified Logic of Writing Circuits

Obviously, when the state of write flip-flop is switched by the delayed phase B pulse, it causes a flux change on the drum surface. This flux change is not sensed, however, as a binary 1 bit because the drum is sensed during playback (reading) for a flux change only at phase A time. Detailed information on the principle of NRZ recording using phase modulation is shown on Figure 2-4.

2.3 DRUM FORMAT

Data from the computer is written on drum tracks that circumscribe the drum cylinder as shown in Figure 2-5. The RM08 has 256 tracks; each data track contains 64 sectors and each sector contains 16 13-bit words (0 through 17 octal). The 13-bit word consists of 12 data bits and a parity bit.

The words within any particular sector are stored consecutively on the track. The first 16 words on the track are for sector 0; the next 16 words for sector 1, etc., as shown in Figure 2-5. The last 16 words on the drum track are words 0 through 17 for sector 77₈. There are 13 clock pulses per word throughout the drum track. The drum also contains a clock pulse track. The clock pulse track supplies clock pulses to the drum control logic at 1.2 µs (60 c/s) intervals to synchronize writing and reading of the drum. There is a 10 µs gap between sectors within each track and a 300 µs gap to separate the beginning and end of each track. A 300 µs gap, where no clock pulses exist, separates the beginning and end of each track.

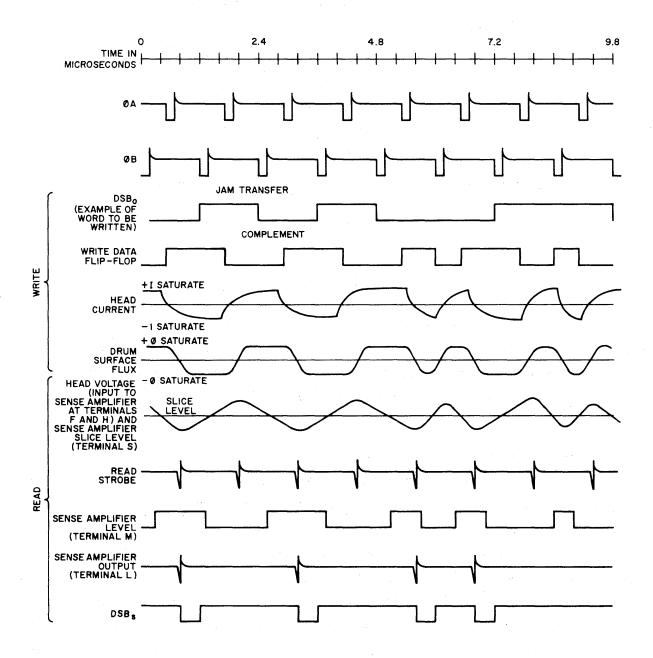


Figure 2-4 Typical Recording and Playback Timing

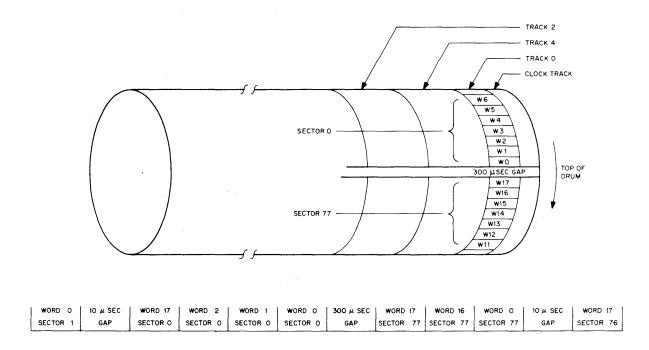


Figure 2-5 Drum Format

Figure 2-6 shows a closer view of the word format in a sector. The words shown are the first word of the track, word 0 of sector 0 and word 1 of sector 0. The first clock pulse (index pulse) following the 300 µs gap does not write a bit; it alerts the drum control circuits of the beginning of timing pulses. The next 12 drum clock pulses write the 12 data bits of the word. After 12 bits are written, an odd parity bit is written; i.e., if the 12 bits contain an even number of 1's, a parity bit of 1 is written to generate off parity. To separate sectors, a 10-µs gap exists after the 16th word of each sector and preceding the first word of the succeeding sector.

2.4 DRUM WRITE CYCLE

As a quick reference source, Table 2-1, Analysis of Instructions for the Write Cycle, is located at the end of this chapter.

In general, the DRCW instruction (see Table 5-1) initiates a drum write cycle in the drum control logic. IOT instruction 6624 must be given initially before DRCW in order to select the proper core memory field, drum field and number of sectors to be transferred. This instruction may be given once if the core memory field, drum field and block size remain the same. The DRCW command normalizes certain control flip-flops in the drum control logic, sets the read/write flip-flop to the write state,

sets the drum 4-state device to idle, sets the data in/out signal to notify the computer data break facility that the transfer direction is out of the computer, loads the DCL from the accumulator, and sets the break request flip-flop to initiate a data break.

NOTE

The drum control logic incorporates a 4-state device to signify drum control status. The four states are IDLE, TRA, ACT, and COMP FLAG. Only one state at a time is entered and, during a normal transfer, the states advance in sequence. Entry into any state disables all other states. The IDLE state indicates that the drum has not been activated by the program or it is waiting for a 200-µs delay to set the TRA state. The TRA state indicates that the drum control is set up to transfer data, but the beginning of the drum track has not been encountered. The ACT state is entered at the beginning of the track to transfer data. The FLAG stage indicates the completion of a sector transfer.

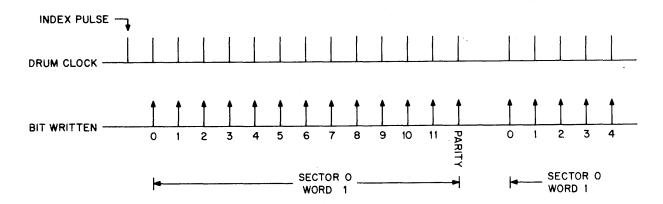


Figure 2-6 Word Format

The break request signal, generated by the break request flip-flop, initiates a computer data break cycle. During the data break cycle, the DFB is loaded from the memory location specified by the DCL and the contents of the DCL are incremented so that the next data break cycle addresses the next higher memory location. The drum control circuits now wait for the execution of the DRTS command (see Table 5-1).

The DRTS command loads the drum track and sector address from the accumulator into the DTA and DSA registers. The DRTS command also loads the 1s SNC from the SNR —— 1s complement of SNR. The DTA address register selects the specified track for the ensuing write cycle, and the DSA selects one sector of the track. The DFB register contents are transferred into the DSB register. The DRTS command also initiates a 200 µs delay to permit the track selection circuits to set up.

After the 200 µs delay, the TRA (transfer) state is set. The SYNC is incremented by 1 to produce the 2s complement of SNR. The first clock pulse of the selected sector (first clock pulse after the gap on the drum) sets the 4-state device to ACT (active). If the sector counter is equal to the sector address (SC = DSA), writing begins immediately. The ACT signal enables the drum clock pulses to generate the shift pulses and the write pulses (phase-A pulses). The first word to be written is shifted into the DSB by the shift pulses. After a data bit is shifted into the most significant bit of the DSB (DSBO), the phase-A pulse complements the write data flip-flop.

With the NRZ writer enabled, the data bit in DSB0 is written on the drum. The control pulses continue shifting the contents of the DSB and writing the DSB0 contents until the 12 data bits and the parity bit are written. After the 13 bits are written, the DSB is again loaded from the DFB and the circuits are set up to write another word, and the break request is sent to the computer to reload the DFB with the next word to be written. Writing continues in this manner until all 16 words of a sector are written. The end of the sector (beginning of the 10-µs gap) sets the drum 4-state device to FLAG if SCOV is a one or sets the 4-state device to TRA if SCOV is a zero. If TRA is set then the next 16-word sector will be written, if Flag is set then it indicates the completion of the data transfer.

2.4.1 Write One Sector-Detailed Description

The 6624 instruction loads the core memory bank, drum field, and puts 01₈ into SNR. The DRCW command (Table 5-1) that is executed by the computer starts the write cycle. The octal code of this IOT instruction is 6605. The execution of 6605 generates IOP1, IOP2, and IOP4 pulses in the computer. (Refer to the PDP-8 Users Handbook or the PDP-8 Maintenance Manual for the explanation of the IOT instruction.) Memory buffer bits 3 through 8 and the IOP pulses are applied to the 4605 Device Selector as shown on Dwg. No. D-RM08-0-4, coordinates C7. (Hereafter, drawing references will show only the last digit of the drawing and the coordinate, e.g., 4C7.) The internal gating structure of the 4605 circuit permits the IOT 6605 instruction to generate IOT 6601 and 6604 pulses (see Table 2-1). Note that the IOT 6601 pulse sets the 4-state device to IDLE (4A5). The 4-state device can be in only one state at a time because the feedback from the current state disables the other three states.

After the DRCW execution, the DCL register contains the memory address of the first word to be written on the drum. The DRCW has set the break request flip-flop; therefore, the computer executes a data break cycle (Table 2-1) to load the DFB from the memory location specified by the DCL register. The contents of the DCL register are incremented so that it addresses the next higher memory location. (Information on the computer data break cycle can be found in the PDP-8 Maintenance Manual.)

The control circuits now wait for the computer to execute the DRTS instruction. The DRTS instruction, 6615, applied MB bits 3 through 8 and the IOP pulses to the device selector (4C7) to generate the IOT 6611 and 6614 pulses. These pulses perform the operations outlined in Table 2-1. In brief, they load the DTA and DSA registers from the accumulator, load the ONE's complement of SNR \longrightarrow SNC, transfer the contents of the DFB into DSB, and trigger the 200-µs delay which sets the TRA state (4B5/6) and +1 to SNC.

The DSB is loaded with the word to be written, and assuming that the 200- μ s delay (4B5), which permits the track selection circuits to set up, is completed, the 4-state device is set to TRA. Note that no phase-A (Φ A) or phase-B (Φ B) pulses are generated since ACT = 0 (1E11, 4C3). Therefore, the DSB is not shifted and no writing occurs.

The TAKE WORD signal (generated during DRTS) is enabled and sets the break request (RQ) flip-flop. This break generates the second word into the DFB. The DFB is transferred to the DSB. At this point, word zero is in the DSB and word ONE is in the DFB.

The index pulse at the beginning of the desired sector generates the START pulse which sets the 4-state device to the ACT state if SC = SA. The drum clock pulses are shaped by PG 1410 (4C2) the output of which triggers the (BLOCK 3.4-µs) and DATA (12-µs) integrating single shots. As long as there are clock pulses, the BLOCK and DATA multivibrators are held in the ONE state. However, in the absence of drum clock pulses, as during the 10-µs gap, the ZERO state is enforced for BLOCK, and during the 300-µs gap the ZERO state is enforced in both BLOCK and DATA. When SC = SA and SNCOV is a zero, the TRA is set, then the BLOCK going to a ONE will set ACT.

If the first four bits of the word to be written are 0011, as shown in Figure 2-7, the ACT signal (3D1) generates the 0B + ACT pulse. This pulse enables the WRITE DATA circuits (3D2) to put the WRITE DATA flip-flop into the proper state to write the designated DSB0 bit at phase A pulse time. The ACT signal gating Φ A (1E11R, 4C3) does not permit the index pulse to generate a phase-A pulse. The second drum clock pulse generates the phase A pulse, and it complements the WRITE DATA flip-flop. The WRITE DATA flip-flop output is coupled to the NRZ Writer Module, Type 4529 to write the designated bit. The ensuing phase-B pulse generates the shift pulse (3B1) to shift the DSB. The phase-B pulse, which was delayed to permit rise time of DSB0, generates the 0B + ACT pulse which again establishes the proper state of the WRITE DATA flip-flop. The next phase-A pulse writes the second bit specified by the DSB0 flip-flop.

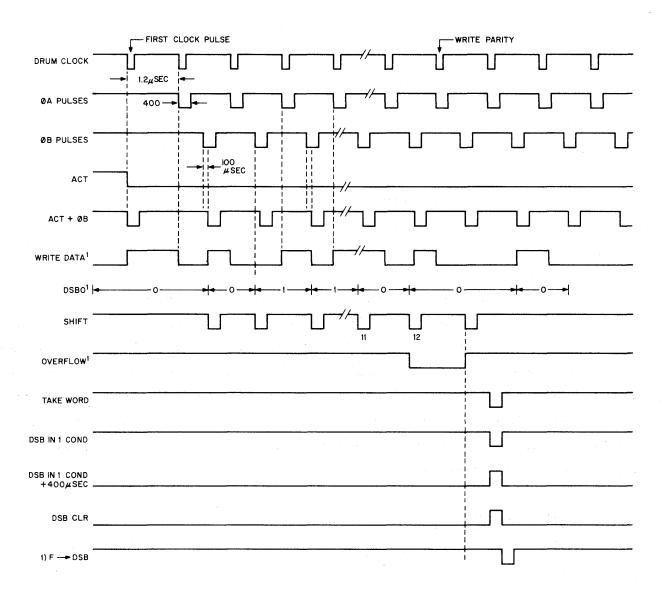


Figure 2-7 Write Cycle Timing

After 11 shifts of the DSB register, DSB2 through DSB11 contain all 0's because the DSBS flip-flop, which is continually reset by the shift pulses, shifts 0's into the DSB. Note that DF—DSB pulse initially sets DSBS; this insures at least 1 bit in DSB2 through DSB11 during the 11 shifts when a word is wirtten in the event that the DSB was originally all 0's. The 12th shift pulse sets the OVERFLOW flip-flop (3C4) since DSB2 through DSB11 are all 0's. The OVERFLOW signal enables the R PARITY flip-flop to write the parity bit. The shift pulses complement the R PARITY flip-flop for each 1 bit that is written. Since the R PARITY flip-flop is initially set, an odd number of 1's leaves the R PARITY flip-flop in the reset state. In this case, the R PARITY signal (1D10-M, 3D2) causes the WRITE DATA flip-flop to reset so that the phase-A pulse writes a 0 parity bit to generate odd parity.

Writing continues until all 16 words of the address sector are written. The drum clock pulse that writes the parity bit of the 16th word of sector 77₈ is the last drum clock pulse before the 10 µs gap. The BLOCK one-shot multivibrator (3C1) reverts to the ZERO state 3.4 µs after the last drum clock pulse. This signal BLOCK 0-3B6) sets the 4-state device to the FLAG state if SNCOV is a 1 or to a TRA state if SNCOV is a 0.

After the FLAG state is set, the actions that follow depend on the computer. If the computer is programmed to write only one sector, the DRSC instruction (octal code 6622) generates the IOP 6622 pulse to sense the FLAG state (1E10M, 4A7). When the FLAG state is 1, the I/O SKIP causes the computer to skip the next instruction and exit from the DRSC loop. The DRSE (code 6621) may then sense the drum control for errors. This is accomplished by the DRSE instruction which generates the IOT 6621 pulses to sense the PE⁰·DE⁰ state (4A8). If no errors occur, the I/O SKIP signal causes the computer to skip the next instruction and exit from the drum routine. If an error occurs, the program will not skip the next instruction which contains a JMP to an error check routine.

2.5 DRUM READ CYCLE

As a quick reference source, Table 2-2, Analysis of Instruction for the Read Cycle, is located at the end of this chapter.

The 6624 IOT is given first. The DRCR instruction loads the DCL from the accumulator, normalizes control flip-flops in preparation for the read cycle, sets the 4-state device to IDLE, sets the DATA IN/OUT signal to DATA IN, and sets the READ/WRITE flip-flop to read. The program execute the DRTS instruction to load the DTA, DSA registers from the accumulator, SNR to SNC (ONE's complement) and after a 200-µs delay plus 1 to SNC and sets the TRA state. If SC = SA then the next index pulse sets the ACT state which enables the drum control circuits to read the drum. Data read from the addressed drum track is strobed into the least significant bit of the DSB register, (DSBS) and the contents of the DSB are shifted. After 12 shifts, the DSB contains the word read from the drum; then parity is checked. If a parity error occurs, the parity error flip-flop is set to indicate the error. The DSB contents

are transferred to the DFB and the break request signal is sent to the computer. The computer enters a data break cycle to transfer the DFB contents into the memory location specified by the DCL register. The DCL contents are then incremented. Transfer continues in this manner until all 16 words of the addressed sector are read. After the last word of the sector is encountered, BLOCK is reset to a ZERO to signify the completion of the sector transfer.

2.5.1 Read One Sector - Detailed Description

The 6624 IOT is given first. The DRCR instruction (octal code 6603) applies the MB bits 3 through 8 and the IOP pulses to the device selector to generate the IOT 6601 and 6602 pulses. Table 2-2 shows the detailed signal flow of the DRCR instruction. In brief, the DRCR instruction sets the IDLE state, clears the READ/WRITE flip-flop, and loads the DCL from the accumulator. The READ/WRITE flip-flop remains clear to signify the READ state. The READ signal causes the DATA IN signal (4B7) to be -3V to signify a DATA IN direction to the data break circuits in the computer.

The DRTS instruction is then executed to load the DTA and DSA registers with the drum track and sector address of the forthcoming read cycle (loads the ONE's complement SNR to SNC). As shown in Table 2-2, the DRTS instruction prepares the control circuits to read the first word. Note that a 1 is inserted into DSB11 (by DSB INI COND + 400 ns) (3C8) and the DSB register is cleared. After 12 shifts, the 1 that was inserted into DSB11 is in DSBF (3B2). Therefore when DSBF is a ONE, it indicates that one word has been read from the drum. The Read Cycle Timing Diagram, Figure 2-8, illustrates this condition.

After TRA is set, the control circuits wait for the index pulse and SC = SA. The index pulse sets the BLOCK one-shot multivibrator (4C1) to START which in turns sets the 4-state device to ACT (4A6). The ACT signal (4C2) enables the drum clock pulses to pulses to pulses A (Φ A), READ STROBE, and phase B (Φ B) pulses. As the drum rotates, the flux changes induce signals into the read heads. The addressed drum read head output is applied to the Type 1537 Sense Amplifier. The READ STROBE, which occurs 0.25 μ s after the phase A pulse, senses the sense amplifier (3C6) and produces a DATA READ pulse when a 1 is read from the drum; no pulse is produced when a 0 is read from the drum. The DATA READ pulse sets the DSBS flip-flop (3C8), and the shift pulse shifts the 1 from the DSBS into DSB11, as it shifts the DSB register.

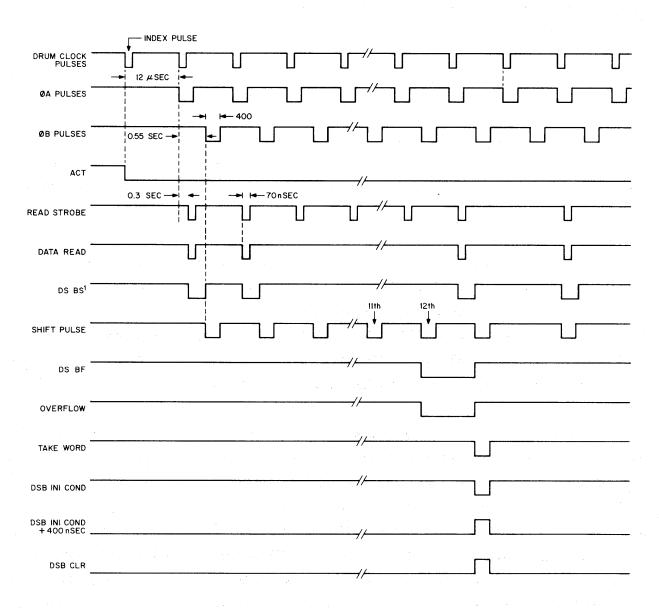


Figure 2-8 Read Cycle Timing

The shift pulse also resets the DSBS flip-flop. If the data bit read from the drum is 0, the DSBS flip-flop remains reset and the shift pulse shifts a 0 into the DSB11 flip-flop. Data transfers continue in this manner until the original 1 bit that was in DSBS is shifted into DSBF. As the 1 is shifted into the DSBF flip-flop, the DSBF1 signal sets the OVERFLOW flip-flop (3C4). The 12 bits read from the drum are in the DSB register. The next phase-B pulse, enabled by READ and OVERFLOW, generates TAKE WORD and DSB INI COND (3C2, 3C3). The DSB INI COND signal checks parity (explained later) and prepares the circuits to read the next word from the drum. The TAKE WORD (3B2) transfers the DSB contents into the DFB and sets the RQ flip-flop (4A2). The next phase-B pulse resets the OVERFLOW flip-flop.

When the RQ flip-flop is set, the word read from the drum is in the DFB. The RQ signal initiates a computer data break cycle to transfer the DFB contents into the memory location specified by the DCL (refer to Table 2-2).

Data transfer continues in this manner until all words of the addressed sector have been read. As the 10-µs gap is encountered, clock pulses cease to occur and the BLOCK multivibrator reverts to the ZERO state. This signal sets the TRA state if SCNOV is 0 and sets flag state if SCNOV is 1. With the flag state set, the program senses the flag state to exit from the read routine. If TRA was set then the next sector will be transferred.

2.5.2 Parity Check

As a word is read from the drum, the DATA READ pulse complements the R PARITY flip-flop (3C4). The R PARITY is initially set. The DATA READ pulse occurs only when a 1 is read from the drum. Since odd parity is generated during the write cycle, the R PARITY flip-flop should be in a reset state after the 12-bit word plus the parity bit are read from the drum. If not, the DSB INI COND pulse sets the PE flip-flop to indicate a parity error.

2.6 PARITY ERROR/DATA ERROR DETECT

A parity error (PE), described previously, occurs when a word is incorrectly read-out of the drum. A data error (DE) is generated when the computer does not answer a break request before another break request is made. The break request signal sets the ER SYNC flip-flop (4A3). The T2D pulse, which occurs during a data break resets the ER SYNC flip-flop. If a data break does not occur, this flip-flop remains set. The next RQ signal is enabled by ER SYNC to set the data error flip-flop.

The DRCF (clear flag) instruction generates the IOT 6611 pulse that resets the DE flip-flop (4A3), DTA (5B1), PE (3C5), and sets IDLE (4A5). Instruction DREF loads the condition of PE and DE into accumulator bits 0 and 1, respectively, to permit programmed evaluation of an error flag. Instruction DREF also generates the IOT 6612 pulse, which clears the AC (0—AC, 4C5) and generates a

delayed 6612D (400 ns) pulse which transfers DE to AC1 (4A4) PE to AC0 (3D5) and the contents of the sector counter to the accumulator $SC_0 \longrightarrow 5$ $AC_7 \longrightarrow 11$. The state of the PE and DE flip-flops is sensed by instruction DRSE and causes a program skip if no error occurs. This condition of PE(1) + DE(1) will set SNCOV to terminate a transfer.

In the ON position, the MAINTENANCE ON/OFF switch (4D2) applies PE⁰·DE⁰ to the gate (1D9F, 4C3) which enables the phase A, phase B, and READ STROBE pulses. Detection of a data error or a parity error inhibits the clock signals so that all data transfer stops and the contents of all registers can be observed to locate the cause of the error. In the OFF position the equipment functions normally and data errors or parity error can be detected via the error flag at the end of a sector transfer. The maintenance SW ON will only operate if the instruction for clearing the error flag is not regenerated and transfer restarted.

2.7 DRUM TRACK SELECTION CIRCUITS

The drum track selection circuits are shown in Dwg. No. E-RM08-0-2. DTA bits 4 through 7 are applied to the Y-selection circuits, and DTA bits 0 through 3 are applied to the X-selection circuits. The addressed X-selection circuit applies the read and write buses to a set of drum read/write heads. The addressed Y-selection circuits provide a single return path for the group of read/write heads addressed by the X selection circuits. Hence the DTA selects a single drum read/write head by the coincidence of the X- and Y-selection lines. For example, when the DTA is clear (DTA = 000000000), the Y0 line and the X0 line select the read/write head that is labeled '0-77₈". The "0-77₈" refers to the 64 sectors written by that read/write head. Similarly, all other read/write heads are labeled with their track and sector address.

FIELD LOCKOUT switches are provided so that data can be retained on certain fields to be available for reading only. There are 16 FIELD LOCKOUT switches (Figure 4-1). Each switch prevents writing on four drum tracks. Switch 0 inhibits tracks 0 through 3; switch 1 inhibits tracks 4 through 7; and, consequently, switch 15 inhibits tracks 74 through 77. The lockout is accomplished as follows.

The DTA4 and DTA5 bits are applied to four decoders (5D5). Each decoder output LO_0 through LO_3 is a logic 1 when the bit contents of DTA4 and DTA5 are 00 through 11, respectively. The WRITE signal is also an input to the decoders. The LO_0 through LO_3 signals are applied to the FIELD LOCKOUT switches as shown in (3D1, 2D2, 2D3). When switch 1 is closed, LO_0 applies a negative potential to the X0 selection to prevent writing on the addressed track 0. Similarly, the other seven switches lock out their associated tracks.

2.8 MECHANICAL DESCRIPTION OF DRUM

The full complement of magnetic heads is mounted on the drum in a series of blocks, with a line of eight heads in each block, and the gaps coplanar at one surface, as shown in the simplified mechanical diagram, (Figure 2-9). The flat surface serves as the pad or slider of a hydrodynamic bearing, using the boundary layer of air clinging to the rotating drum as a lubricating or self-pressurizing medium. A single thin strip of spring steel connects each magnetic head/bearing pad to the drum frame. The spring steel reed serves as a combined motion pivot, loading spring, and mounting cantilever. The action of this simple mechanical system for placing the magnetic head pad in close proximity to the drum surface when the drum is at operating speed is illustrated in Figure 2-10.

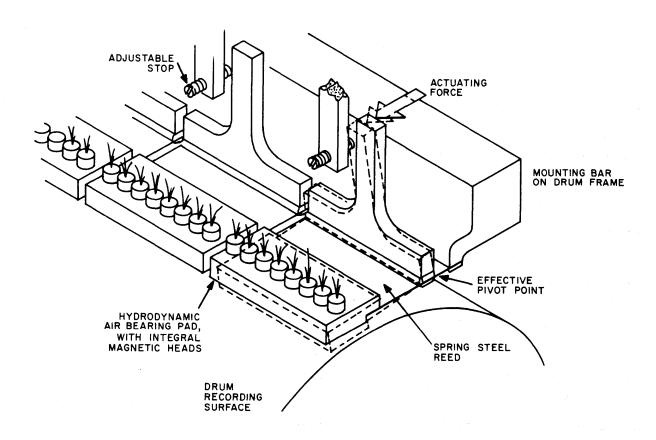


Figure 2-9 Drum Head Mounting

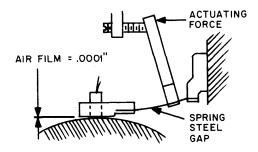


Figure 2-10 Operating Position of the Head Pad

The mechanical actuator moves the head into close proximity of the drum surface when the drum is up to speed. As the drum comes to speed, a centrifugal switch, mounted on the motor end, closes and sets a time delay relay (red cap). The relay energizes in 1.5 min and sets another time delay relay (yellow cap) which supplies actuating power to the linear motor actuator for 6s. After the linear motor pulls in the heads, a holding coil, which is energized from rectified ac, holds in the heads. The 1.5-min delay permits the drum to reach full speed prior to actuation. The 6-s interval should not be exceeded because the linear motor has a very short duty cycle and can burn out if left energized. A circuit breaker that is thermally actuated by the linear motor current provides further protection for the motor.

Normal shut down of drum power on any power failure will instantly raise the heads. Motor burnout, although not anticipated, results in speed loss so that the centrifugal switch opens and raises the heads.

A fuse mount, located under the right-hand front corner of the cabinet, contains a switch that can be used to actuate the heads. The drum centrifugal switch must be closed to operate this switch.

If holding coil fails to hold at the end of the pull-in cycle, the manual switch must be opened and closed to restart the cycle.

2.9 POWER SUPPLY AND DISTRIBUTION (RM08 DRUM SYSTEM)

The 120 Vac for the RM08 Serial Drum is supplied by a 120-Vac outlet. The ac is applied to the Type 832 Power Control in the RM08 Drum System (refer to Dwg. No. D-RM08-0-12). Relay contacts in the RM08 Drum 836 Power Control connect terminal 1 to 2 when the relay is energized. The relay is energized by -15V from the PDP-8 power supply (Dwg. No. PW-D-RM08-0-12 and RS-836). With the circuit breaker on and the REMOTE/LOCAL switch in the REMOTE position, ac power is supplied to relay contacts K1 and K2 when the -15V from the PDP-8 computer energizes the relay in the 836 Power Control. In the LOCAL position, ac power is applied to the K1 and K2 relays when the circuit

breaker is on. The K2 contacts enable the fast-on delayed-off ac power. The K1 contacts apply ac to the time delay relay K3 which enables the delayed-on fast-off ac power.

The fast-on delayed-off ac power is applied to the blower fan, drum motor, and the +10V and -15V power supply in the Type 779 Power Supply. The delayed-on fast-off ac power is applied to the dual 15-V power supply in the Type 779 Power Supply only, (refer to Dwg. No. D-RM08-0-). The red terminal of the 779 Power Supply is grounded, and the yellow terminal remains unconnected. This provides -30V at the green terminal which is used in the NRZ writer, read sense amplifier, and the X- and Y-selection modules.

When power is initially applied to the RM08 Drum System, a DDC CLEAR pulse is generated to normalize control flip-flops in the drum control circuits. This is accomplished by the Type 4401 module (Dwg. No. D-RM08-0-) supplying DDC CLEAR pulses to the system. An RC network delays the -15V to terminal V of the 4401 module; shortly after the application of power, terminal V is sufficiently negative to inhibit the clock pulses, and the drum can function normally.

Tables 2-1 and 2-2 show the analysis of instructions for the write and read cycle, respectively. These tables provide a reference to detailed signal flow during a write or read cycle.

Table 2-1
Analysis of Instructions for Write Cycle

Instruction, Operation, or Signal	Function
DRCW (6605)	Generates IOT 6601 and 6604 pulses (4C7).
IOT 6601 pulse	(Via 1E11W, (4B1) Clears, RQ, READ/ WRITE, ER SYNC, DE, and via 1C11V (4A4) sets IDLE.
	Generates DDC CLEAR (4B4) which clears OVERFLOW, R PARITY, WRITE DATA, PAR ERROR (3C4, 3C5).
IOT 6604 pulse	Transfers AC to DCL (5B1)
	Clears AC (4C5)
	Sets RQ, WRITE, and ER SYNC (4A2, 4A3).
DATA BREAK CYCLE	DCL to MA signal resets RQ and generates DRA (4B1)
	DRA increments the DCL contents (DCL14–1C6, 5C6) and clears DFB (3A2)
	T2A pulse from computer (4B2) resets ER SYNC and generates T2D
	T2D transfers MB to DFB (3A).

Table 2-1 (continued) Analysis of Instructions for Write Cycle

Instruction, Operation, or Signal	Function
DRTS (6615)	Generates IOT 6611 and 6614 pulses (4C7).
IOT 6611 pulse	Clears DTA and DSA
	Clears PAR ERROR (3C5)
	Clears DE (1C09-4B3).
IOT 6614 pulse	Transfers AC to DTA and SA (5C1)
	Clears AC (4C5)
	Generates TAKE WORD (3C2)
	SNR-→SNC
	Triggers 200-µs delay (4B5) that sets TRA
	+1 to SNC.
TAKE WORD	Set RQ (4B2)
	Generates DSB INI COND (3C3).
DSB INI COND	Clears DSBF (3B2) and DSBS (3C8)
	Generates DFB → DSB (3C3) which sets DSBS (3C8), and transfers DFB and DSB (3C3).
	Generates DSB INI COND + 400 ns which sets R PARITY.
ΦA pulse	Complements WRITE DATA (3C5)
	Generates ΦB pulse (4C5).
ΦB pulse	Resets OVERFLOW if OVERFLOW = 1 (3C4)
	Generates SHIFT pulse if OVERFLOW=0 (3B1)
	(Delayed) generates OB+ACT pulse (3D2).
DRSC (6622)	Generates IOT 6622 pulse which senses the flag state (4A7).
IOT 6624 pulse	Loads AC ₁₀ , AC ₁₁ into DFR (21B2), loads AC ₀ through AC ₅ into SN register.
	Loads AC6 through AC8 into DCLO-2 (5A1).
IOT 6612	0— → AC
	Generates 6612D
	$\begin{array}{c} 6612D \text{ loads PE} \longrightarrow AC_0, DE \longrightarrow AC_1, \\ SC_{0 \longrightarrow 5} \longrightarrow AC_{7-11}. \end{array}$

Table 2-2
Analysis of Instruction for Read Cycle

Instruction, Operation, or Signal	Function
DRCR (6603)	Generates IOT 6601 and 6602 pulses (4C7).
IOT 6601 pulse	(Via 1E11W, (4B1) Clears RQ, READ/WRITE, ER SYNC, DE and via 1C11V (4A4) sets IDLE
	Generates DDC CLEAR (4B4) which clears OVERFLOW, R PARITY, PAR ERROR, WRITE DATA (3C4, 3C5).
IOT 6602 pulse	Clears DFB
	Transfers AC to DCL
	Clears AC.
DRTS (6615)	Generates IOT 6611 and 6614 pulses (4C7).
IOT 6611 pulse	Clears DTA and DSA
•	Clears PAR ERROR (3C5).
	Clears DE (1C09-4B3).
IOT 6614 pulse	Transfers AC to DTA and SA (5C1)
	Clears AC (4C5)
	Generates DSB INI COND (3C3)
	SNRSNC
	After 200 µs sets TRA, and +1 to SNC
DSB INI COND	Clears DSB (3C8) and DSBF (3B2)
	Sets PAR ERROR if READ · ACT · R PARITY = (3C5)
	Clears DSBS (3C8)
	Generates DSB INI COND + 400 ns which sets R PARITY (3C4) and DSB11 (3B8).
ФА pulse	Generates READ STROBE (4C)
	Generates ΦB pulse (4C8).
ΦB pulse	Generates SHIFT PULSE if OVERFLOW = 0 (3B1)
	Resets OVERFLOW (3C4) if OVFLO(1)
	Generates TAKE WORD when OVERFLOW = 1 (3C1, 3C2).

Table 2–2 (continued) Analysis of Instruction for Read Cycle

Instruction, Operation, or Signal	Function
TAKE WORD	Generates DSB INI COND (3C3)
	Transfers DSB to DFB during READ (3B2)
	Set RQ (4B2).
DATA BREAK CYCLE	DCL to MA signal resets RQ and generates DRA (4B1)
	DRA increments DCL contents (DCL14-1C6, 5C6)
	T2A pulse from computer (4B2) resets ER SYNC and generates T2D, T2D clears DFB (3A1).
	T2 generates DFB → MB (internal to PDP-8)
DR SC (6622)	Generates IOT 6622 pulse which senses FLAG (4A7).
DRFS (6624)	Generates IOT 6624 pulse (4C8).
IOT 6624 pulse	Loads AC ₁₀ , AC ₁₁ into DFR (21B2), loads AC ₀ through AC ₅ into SN register
	Loads AC ₆ through AC ₈ into DCL 0-2 (5A1).
IOT 6612	Same as write cycle.

CHAPTER 3 INTERFACE

All logic signals which pass between the computer and the serial drum are standard DEC levels or standard DEC pulses. A standard DEC level is either ground (0.0V to -0.3V) or nominal -3V. Standard DEC pulses are nominal 2.5V in amplitude (2.3V to 3.0V) and are 0.4 µs in duration (500 kc modules). Positive pulses are referenced to ground (0.0V to +2.5V) and negative pulses are referenced to ground.

Standard DEC ground potential signals are symbolized by an open diamond (—>) and standard DEC negative signals by a solid diamond (—>). Standard DEC positive pulses are also represented by an open diamond, and negative pulses by a solid diamond.

The input and output signals of the RM08 pass through connectors (1F2, 1F3, etc.). The connectors, and associated input and output signals are contained on the logic drawings (refer to Chapter 7). Refer to the PDP-8 Maintenance Manual for interface information in and out of this unit.

CHAPTER 4 INSTALLATION AND OPERATION

4.1 SITE REQUIREMENTS

The installation site must provide floor space at least 24 in. wide and 28 in. deep to accommodate the serial drum. At least 9 in. must be provided in front of the cabinet and 15 in. at the back to allow opening of the doors for maintenance.

Power to the RM08 is supplied from a 115 Vac output. Current drawn from the power source is 8.0A starting surge and 5.0A running.

The ambient operating temperature recommended is from 70° to 85°F.

4.2 CONTROLS AND INDICATORS

Manual control of the serial drum is accomplished through switches on the switch panel (Figure 4-1). Table 4-1 lists the switches and provides a brief descrition of their functions.

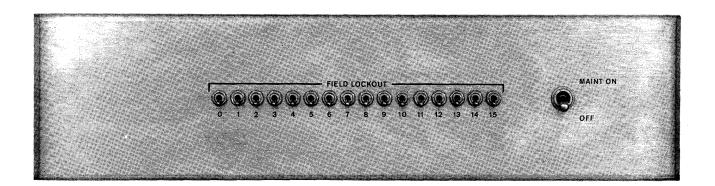


Figure 4-1 Field Lockout Switch Panel

Table 4-1
Controls, Indicators, and Switches for RM08 Serial Drum

Control, Indicator, Switch	Function
MAINT ON/OFF (Field Lockout panel)	Allows maintenance personnel to select the normal or stop-on-error mode of operation. In the OFF position the equipment functions normally and data errors or parity errors can be detected only by the error flag at the end of a sector transfer. In the ON position detection of data error or parity error by the machine inhibits generation of clock signals (\$\PhiA\$, Read Strobe, and \$\PhiB\$) so that all data transfer stops and the contents of all registers can be observed to locate the cause of the error.
LOCAL/REMOTE (832 Power Control)	In the REMOTE position, the PDP-8 computer controls the application of power to the serial drum. In the LOCAL position, power is supplied to the serial drum. In both LOCAL and REMOTE positions, the circuit breaker must be on before power is applied to the serial drum. In the OFF position power is turned off from the serial drum.
ON/OFF (832 Power Control)	Applies ac power to the serial drum. The ac power is supplied from the computer; therefore, power must be turned on at the computer before this switch is effective.
FIELD LOCKOUT (16 Switches Field Lockout panel)	Each switch can control the inhibiting of a group of 4 consecutive tracks (4096 words) during writing so that the information stored on those tracks cannot be accidentally destroyed.

4.3 INDICATOR PANEL

The indicator panel lamps (Figure 4-2) provide visual indication of the machine status and register contents. The functions denoted by these lamps are shown in Table 4-2.

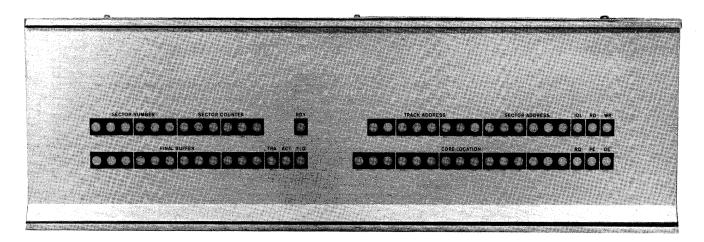


Figure 4-2 Indicator Panel

Table 4–2 Indicator Panel Lamps

Indicator	Function
SECTOR NUMBER (6)	Light to indicate 1's in the sector number register.
SECTOR COUNTER (6)	Light to indicate 1's in the sector counter.
FINAL BUFFER (12)	Light to indicate 1's in the drum final buffer.
TRACK ADDRESS (8)	Light to indicate 1's in the drum track address register.
SECTOR ADDRESS (6)	Light to indicate 1's in the drum sector address register.
CORE LOCATION (15)	Light to indicate 1's in the drum core location counter.
RDY	Lights to indicate that the drum is up to speed and ready for transfers.
TRA	Lights to indicate receipt of IOT pulse. It also indicates that the machine has been taken out of IDLE state and is waiting for clock pulses to be read from the drum. This indicator assures that the drum is in the correct position before initiating a transfer.
ACT	Lights to indicate that the machine has been taken out of the TRA (transfer) state and is actively engaged in a data transfer.
FLG	Lights to indicate that a sector transfer has been completed and the machine has been taken out of the active state. The machine remains in this state until the flag is cleared when the machine is set to either the IDLE or the TRA state.
IDL	Lights to indicate that the drum is in the IDLE state.
RD/WR	Light to indicate that the machine is in either the read or write mode.
RQ	Lights to indicate that a data request signal has been sent to the computer to request a data break to transfer a word.

Table 4–2 (cont) Indicator Panel Lamps

Indicator	Function
PE	Lights to indicate that the machine has detected a parity error after read-in from drum to core. If the MAINT ON/OFF switch is OFF when a parity error occurs, the drum error flag is set to 1; if the switch is ON, the IDLE state is set and the transfer terminated.
DE	Lights to indicate that the machine has detected a data error, because the data request signal from the drum was not answered before another request was given.

CHAPTER 5 PROGRAMMING

5.1 <u>INSTRUCTIONS</u>

The operation of the RM08 Serial Drum is controlled by the IOT instructions listed in Table 5-1.

Table 5–1
Type RM08 Serial Drum Instructions

Octal Code	Mnemonic Symbol	Operation
6603	DRCR	Load the drum core location counter with the core memory location information in the accumulator. Prepare to read a number of sectors of information from the drum into the specified core location.* Clears the AC on completion.
6605	DRCW	Load the drum core location counter with the core memory location information in the accumulator. Prepare to write a number of sectors of information into the drum from the specified core location.* Clears the AC.
6611	DRCF	Clear completion flag and error flag.
6612	DRES	Load the condition of the parity error and data timing error flip-flops of the drum control into accumulator bits 0 and 1, respectively, to allow programmed evaluation of an error flag. Load the condition of the drum sector counter into the accumulator bits 6——11, for program evaluation of the drum address. First, clears the AC then loads.
6615	DRTS	Loads the drum address register with the track and sector address held in the accumulator. Load the contents of the drum field and sector number register into the drum track register (DTAO, DTA1) and sector number counter, respectively. Clear the completion and error flags, and begin a transfer (reading or writing).* Clears the AC.
6621	DRSE	Skip the next instruction if the error flag is a 0 (no error).
6622	DRSC	Skip next instruction if the completion flag is a 1 (sector transfer is complete).

^{*}The sector, track, and core memory address are suitably incremented and allow transfer of the next sequential sector without respecifying addresses up to 64 sectors.

Table 5-1 (continued)
Type RM08 Serial Drum Instructions

Octal Code	Mnemonic Symbol	Operation
6624	DRFS	Load the drum field register with the contents of the accumulator bits 10 and 11 (ACO ₁₀ , ACO ₁₁ = Field 0). Load the sector number register with the contents of the accumulator, bits 0 through 5, to specify the number of sectors to be transferred (1 to 100g).** Load the three most significant bits of the drum core location register (DCL ₀₋₂) with the contents of the AC bits 6, 7, 8, to specify the core memory block to be used during the drum transfer. If the DRFS is not given before each DRTS instruction, the drum will transfer the field and sector number left in the drum field and sector number register.
		If memory blocks are changed (4K), then 6624 must be given before 6605 in order to break to the correct extended memory block.

^{**100&}lt;sub>8</sub> = 00

5.2 DRUM FORMAT AND PROGRAM TIMING

Chapter 2 explained the drum format and showed diagrams of the drum format and word format. A sector transfer begins when the continuously rotating drum reaches the index mark 1.2 µs before the beginning of the data in a selected track and sector.

Because the selection of the track read-write head requires 200 µs of stabiliaztion time for continuous transferring, a new track must be specified during the first 200 µs of the 300-µs interval. During transfer, if a data timing or parity error occurs, the track and sector address are not advanced and operations stop at the conclusion of the sector transfer. This feature allows the program to sense for error conditions and to locate the track and sector where transmission fails.

The drum completion flag is set to 1 upon completion of a transfer, causing a program interrupt. The flag is cleared either by a clear flag (DRCF) or automatically when one of two transfer instructions (DRTS, DRCN) is given.

The error flag, which should be checked at the completion of each transfer, indicates either of the following conditions.

- a. A parity error has been detected after reading from drum to core.
- b. The data break request signal from the drum was not answered within the required 16-µs period. This condition can occur if other devices with higher priority are connected to the data break

facility. Thus, in reading from the drum the data work stored in core memory is incorrect; in writing on the drum, the next word has not been received from the computer.

5.3 PROGRAMMING SUBROUTINES

The following program examples indicate the operation of the drum system in single and multiple sector transfers.

		Subroutine to Transfer (I	Read) One Sector
(1)		CLA	/Calling sequence
(2)		TAD ADDR	/Initial core memory address
(3)		JMS READ	
(4)		1000	/10 sectors, memory field 0, drum field
(5)		0	/Track and sector address
(6)	READ	0	
(7)		DRCR	/DRCW to write
(8)		TAD I READ	/Load AC with sector count (AC0-5)
			/Memory field (AC6-8), drum field (AC9-11)
(9)		DRFS	/Load sector counter (any value up to 77), Load memory field register, and load drum field register
(10)		ISZ READ	·
(11)		CLA	
(12)		TAD I READ	/Load AC with track and sector address
(13)		DRTS	/Load serial drum DTA and start transfer
(14)		DRSC	/Done?
(15)		JMP1	/No
(16)		DRSE	/Errors?
(17)		JMP ERR	/Jump to error check routine
(18)		ISZ READ	
(19)		JMP I READ	/Return

The first instruction (CLA) clears the accumulator so that the core memory starting address of the data block to be transferred can be loaded into the accumulator by the second instruction (TAD ADDR). The third instruction is a jump to subroutine at address READ. In executing this instruction the contents of the program counter (which now contains the address of the fourth memory location) are stored in the sixth memory location (designated READ), the contents of the accumulator are unchanged, and program control advances to the seventh memory location. The DRCR instruction is executed to transfer the initial

core memory address from the accumulator into the drum core location counter and to establish the read status in the drum. The next instruction TADs indirectly from the READ location. At this time the READ location contains the 12-bit address of location four, which was deposited here as the contents of the program counter during the execution of the third instruction. Therefore, the TAD instruction loads the accumulator with sector number, drum field, and core field. The DRFS instruction loads the drum with the sector number, drum field, and core field. The ISZ READ again increments location READ and then loads it into the AC. This TAD loads the track and sector address. The DRTS instruction transfers the track and sector information contained in the accumulator into the DTA and DSA registers, clears both drum flags, and initiates transfer. The DRSC instruction senses the drum completion flag and increments the contents of the program counter if the flag is a 1, thus indicating that the transfer is not complete. The program advances to instruction 15 which is a jump back to location 14 to check the flag again. When the flag indicates that the transfer has been completed, the program advances to the instruction 16 which is the DRSE instruction. The DRSE instruction senses the error flag and skips the next instruction if no error has been detected. If an error has been detected, the error flag is 1 and the program advances to the next instruction to transfer program control to the error check routine. Finding no drum error, the program advances to the ISZ READ instruction. The next-to-last instruction is the ISZ at address READ. The READ location contains the address of the track and sector address (location 4). The ISZ instruction increments the contents of READ so that it contains the address of the RETURN to the main program. Therefore, the JMP I READ instruction returns program control to the main program.

5.4 FIELD LOCKOUT SWITCHES

The FIELD LOCKOUT switches (Figure 4-1) permit data to be retained on certain tracks where it is available for reading only. Turning a LOCKOUT SWITCH to the ON position inhibits writing on its associated track addresses. The octal address inhibited by each switch are shown below.

Switch	Address	Switch	Address
0	0000-377	8	4000-4377
1	0400-777	9	4400-4777
2	1000-1377	10	5000-5377
3	1400-1777	11 .	5400-5777
4	2000-2377	12	6000-6377
5	2400-2777	13	6400-6777
6	2000-3377	14	7000-7377
		15	7400-7777

CHAPTER 6 MAINTENANCE

Maintenance of the Type RM08 Serial Drum consists of a test and maintenance program MAINDEC-08-D5AA-D, procedures repeated periodically as preventive maintenance, and tasks performed after equipment malfunction as corrective maintenance. Maintenance activities require use of the equipment (or equivalent) listed in Table 6-1, and standard hand tools, cleansers, test cables, and probes.

Table 6–1 Maintenance Equipment

Equipment	Manufacturer	Model		
Multimeter	Triplett/Simpson	630-NA/260		
Oscilloscope	Tektronix	540 Series		
Variable Power Supply	DEC	734		
System Module Extender*	DEC	1954		
System Module Puller*	DEC	1960		
Diagnostic Program	DEC	Digital-5-55-M		

^{*}One supplied with the equipment

If it is necessary to remove modules, use the Type 1960 System Module Puller. Turn off all power before extracting or inserting modules. Carefully hook the small flange of the module puller over the center of the module rim, and gently pull the module from the panel. Use a straight even pull to avoid damage to plug connections or twisting of the printed-wiring board. Since the puller does not fasten to the module, grasp the rim of the module to prevent it from falling.

To gain access to adjustment controls on the module, or to points for signal tracing, remove the module, and insert a Type 1954 System Module Extender into the proper module slot in the panel, and then reinsert the module into the extender.

6.1 PREVENTIVE MAINTENANCE

Perform preventive maintenance tasks prior to initial operation of the equipment and periodically during its operating life. Perform these tasks in accordance with a reasonable schedule to discover progressive deterioration, to correct minor damage, and thus forestall future failure. Compile a log book to record data found during the performance of preventive maintenance to indicate the rate of circuit operating deterioration and provide information to determine when components should be replaced.

Preventive maintenance tasks consist of mechanical checks such as cleaning and visual inspections, checks of specific circuit elements such as the power supply, clock timing, sense amplifiers, and magnetic heads, and marginal checks to aggravate borderline conditions or intermittent failures so that they can be detected and corrected. All preventive maintenance tasks should be performed every six months or 1,000 equipment operating hours, whichever occurs first.

6.1.1 Mechanical Checks

To assure good mechanical operation of the equipment, perform the following steps and the indicated corrective action for any substandard conditions that may be found:

- a. Clean the exterior and the interior of the equipment cabinet using a vacuum cleaner or clean cloths moistened in nonflammable solvent.
- b. Clean the air filter at the bottom of the cabinet. Remove the filter by removing the fan and its housing which are held in place by two knurled and slotted captive screws. Wash the filter in soapy water, dry in an oven or by spraying with compressed gas, and spray with Filter-Kote (procured from Research Products Corporation, Madison, Wisc.).
 - c. Lubricate door hinges and casters with a light machine oil. Wipe off excess oil.
- d. Visually inspect the equipment for completeness and general condition. Repaint any scratched or corroded areas with DEC blue enamel number 3277-1565.
- e. Inspect all wiring and cables for cuts, breaks, fraying, deterioration, kinks, strain, and mechanical security.
- f. For mechanical security, inspect switches, knobs, jacks, connectors, transformers, fan, capacitors, and lamp assemblies.
 - g. Inspect modules for proper seating in the racks.
 - h. Inspect power supply capacitors for leaks, bulges, or discoloration.

6.1.2 Power Supply Checks

Check the output voltage and ripple content of the Type 779 Power Supply. Check the +10V output between the yellow (-) and orange (+) connectors to assure that it is between 9.5V and 11.0V with less than 800 mV ripple. Check the -15V and the +15V outputs (green to yellow and red to yellow, respectively) to assure that they are between 14.5V and 16.0V with less than 400 mV ripple.

These supplies are not adjustable; thus if the output voltage or ripple content is not within the tolerance specified, the supply is defective.

6.1.3 Timing Checks

Using the oscilloscope and referring to Dwg. No. D-RM08-0-4, check the timing of the Type 4303 Integrating Single Shots at location 1C4, 1C13 and the Type 1304 Delay at location 1C15. If necessary, adjust the timing of these modules by turning the potentiometer screw which is accessible through a hole in the handle.

Check the single-shot by observing the 1 output at 1C4W while triggering the oscilloscope on 1C4K. During each revolution of the drum, the single-shot is triggered every 1.2 µs for approximately 17 ms during data reading and receives no pulses during the 300-µs gap. The output at terminal 1C4W should be at ground level during the gap, drop to -3V at the first triggering pulse, and remain at -3V for 3.4 µs after the last triggering pulse is received before reverting to ground potential. The output at 1C13W should be at 0V for 7 µs during the 10-µs gaps between the 64 sectors and at 0V for 300 µs during the large 300 µs gap. Any other time it should be at ground.

Check the timing of the delay module by observing the negative read strobe pulse at terminal 1C15E while triggering the oscilloscope on the ΦA pulse at 1C14J. Read strobe pulses should follow ΦA pulses by approximately 0.25 μs . Observe the read strobe pulses and the amplified output of a magnetic read head by connecting the second input of the dual-trace oscilloscope to terminal 1E25S. It is important that the read strobe pulses occur at the negative peak of the sinusoidal read signal. Measurements should be made using several different heads, and the read strobe pulse should be adjusted for an average of the measurements to eliminate large differences in peak playback time.

6.1.4 Drum Sense Amplifier Checks

The Type 1537 Drum Sense Amplifier modules at locations 1C1 (clock track) and 1E25 (data track) are checked for proper slice or threshold level at terminal S. This measurement can be made with the oscilloscope by measuring the amount by which the base line shifts above ground when the signal is connected to the input. The clock track sense amplifier slice level should be +100 mV. The data track sense amplifier slice level should be +150 mV. Adjustment of the slice level can be achieved by turning the potentiometer screw which is accessible through a hole in the module handle.

6.1.5 Drum Head Mounting Adjustments

Adjustment of the magnetic heads is provided by the stop screw for each pad of heads and its actuating arm, as shown in Figure 6-1. With this stop screw properly positioned, the actuating arm moves the pad to a position where the reed is slightly bent and the pad is tangent to the drum surface at the line of head gap. These adjustments are made at the factory and under normal circumstances should not have to be changed, at least no more than minor adjustment. Should adjustment be necessary, however, proceed in the following manner.

a. Connect an oscilloscope to 1E25S to observe the preamplifier output for the drum head in question.

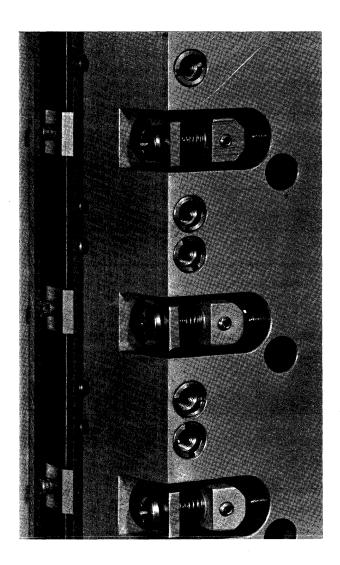


Figure 6-1 Stop Screw Position

- b. Set the DTA to address the drum head in question. Drawing No. BS-E-RM08-0-2 shows the bar and pad location and the octal address of each drum head.
 - c. Set the drum control status to read.
- d. Using a 5/64 hexagonal for socket heads, adjust the stop screws until a maximum output is noted on the oscilloscope as shown in Figure 6-2. The adjustment screw is located on the right-hand side of each bar as one views the drum as shown in Figure 6-1.

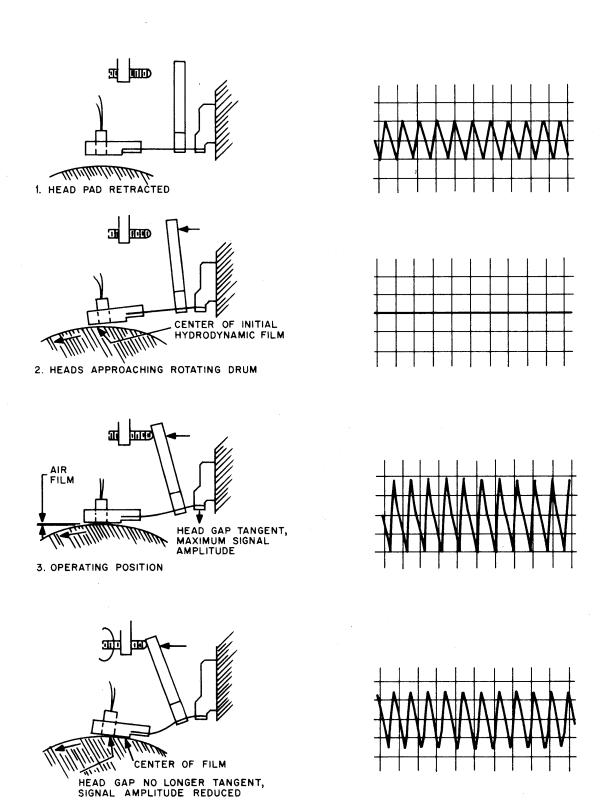


Figure 6-2 Operating Positions of Head Pad

4. ADJUST STOP BACKED OF TOO FAR

CAUTION

If head adjustment is attempted with diode boards in place, make sure that the adjustment wrench is placed and/or insultated to prevent shorting connections or components to ground.

The best method of making this check is to run a program in which the patterns of all 0s, all 1s, or alternate 1s and 0s are written on the selected track, then read the data and monitor the output of the selected track. If data on the selected track is to be retained, it should be read into core memory before proceeding with this adjustment. Rewrite the selected track and read the recorded signal after every adjustment.

6.1.6 Pad Leveling Adjustment

The amplitude of head playback signals among the eight heads in each pad is set as uniformly as possible by using the pad leveling screws which are accessible at the outer surface of each bar, approximately adjacent to the upper and lower edges of each pad. This may be checked on head number 0 (sectors 0-77) and 7 (sectors 0-77) (top and bottom heads) with secondary reference to heads 2 and 7. Clockwise rotation of a pad leveling screw tends to increase signal amplitude at that end of the pad. Continuously write and read the selected heads always alternating between the two.

6.1.7 Marginal Checks

Marginal checks are performed to aggravate borderline conditions within the logic to reveal observable faults. Therefore, these conditions can be corrected during scheduled preventive maintenance to forestall possible future equipment failure. These checks can also be used as a troubleshooting aid to locate marginal or intermittent components, such as deteriorating transistors. The checks are performed by operating the equipment logic circuits from an external, adjustable power source, such as the DEC Type 734 Variable Power Supply.

Raising the bias voltage above +10V is equivalent to lowering the amount of base drive on a particular transistor. This in turn simulates a lower gain driving transistor, thus raising the bias voltage tends to indicate low gain transistors. Lowering the bias voltage below +10V simulates a condition where the voltage drop across the previous driving transistor (V_{CE}) has increased. This tends to indicate high V_{CE} drop (leakage) transistors or low gain driving transistors. The -15V supply margins are not checked in the serial drum because to raise or lower the -15V does not affect the majority of control logic, since it is the collector load voltage and is usually clamped to -3V. The +10V margin should be about $\pm 5V$.*

^{*}The 1537 Sense Amplifier, 1C1 and 1E25, has only $\pm 2V$ margins on $\pm 10V(B)$.

By recording the level of bias voltage at which circuits fail, progressive deterioration can be plotted and expected failure dates predicted. Therefore, these checks provide a means of planned replacement. Marginal checks of the +10 (A) supply (top switch at the left of the rack) to rack E varies the slice level on the drum sense amplifier modules and therefore is a valuable tool in verifying the capability of the machine to read and write on the drum surface. Normally increasing the +10 (A) supply by three or four volts also increases the slice level and causes bits to be dropped out. Decreasing the +10 (A) source by three or four volts usually lowers the slice level and causes bits to be picked up.

Marginal check terminals are provided on color-coded connectors which are connected in common to all racks, so that an external power supply can be attached to any connector to marginal check all racks. The color coding of these connectors from top to bottom is as follows:

Green: +10 Vdc marginal-check supply

Red: +10 Vdc internal supply

Black: ground

Blue: -15 Vdc internal supply

Yellow: -15 Vdc marginal-check supply

Three single-pole single-throw switches at the end of each rack of logic allow selection of either the normal internal power supply or the external marginal-check power supply for distribution to the logic. The top switch selects the +10V supply routed to terminal A of all modules in that rack. In the down position the fixed internal +10V supply connected to the red terminal is supplied to the modules, and in the up position the marginal-check voltage supplied to the green terminal is supplied to terminal A of the modules. The center switch performs the same selection as the top switch for connection of a nominal +10V level to terminal B of all modules. The bottom switch selects the -15V supply to be routed to terminal C of all modules. In the down position, the fixed -15V output of the internal power supply, received at the blue terminal, is supplied to the modules; while in the up position, the marginal-check voltage, connected to the yellow terminal, is supplied to terminal C of all modules.

To perform marginal checks, use the following procedure.

- a. Connect the external marginal-check power supply to the colored connector on any rack between the green (+) and the black (ground) terminal.
- b. Energize the marginal-check power supply and adjust the outputs to supply the nominal +10 Vdc.
 - c. Set the top switch on the rack to be checked to the up position.
- d. Start equipment operation in a repetitive pattern or in a routine which fully utilizes the circuits in the rack to be tested. The diagnostic drum program, MAINDEC-08-D5AA-D, obtainable from the Digital Program Library should be used unless a user has developed a special maintenance program.

- e. Lower the +10V marginal-check power supply until normal system operation is interrupted.

 Record the marginal-check voltage. At this point marginal transistors can be located and replaced.
- f. Start equipment operation, then decrease the +10V marginal-check supply until normal operation is interrupted. At this point record the marginal-check voltage. Transistors can again be located and replaced.
 - g. Stop operation and return the top switch to the down position.
 - h. Repeat steps b through g for the center switch on the logic rack that is being checked.
 - i. Repeat steps b through h for each rack of logic to be checked.
 - j. Deenergize and/or disconnect the external marginal-check power supply.

6.2 CORRECTIVE MAINTENANCE

No special test equipment nor tools are required for corrective maintenance other than a broad bandwidth oscilloscope and a standard multimeter. The best corrective maintenance tool is a thorough understanding of the system logic. Persons responsible for maintenance should become thoroughly familiar with the system concept and the operation of specific circuits as described in Chapter 2; program techniques, described in Chapter 5; the engineering drawings, presented in Chapter 7; and the location of mechanical and electrical components.

Diagnosis and remedial action for a fault condition is performed in the following phases:

- a. Preliminary investigation to gather all information and to determine the physical and electrical security of the system.
- b. System troubleshooting to locate the fault to within a module through the use of diagnostic programming, signal tracing, or aggravation techniques.
 - c. Circuit troubleshooting to locate defective parts within a module.
 - d. Repairs to replace or correct the cause of the malfunction.
 - e. Validation tests to assure that the fault has been corrected.
 - f. Log entry to record pertinent data.

6.2.1 System Troubleshooting

Do not attempt to troubleshoot the drum system without first gathering all information possible concerning the fault, as outlined under Preliminary Investigation.

Commence troubleshooting by performing that operation in which the malfunction was initially observed, using the same program. Thoroughly check the program for proper control settings. Careful checks should be made to assure that the serial drum is actually at fault before continuing corrective maintenance procedures. Faults in equipment transmitting or receiving information or improper connections

of the system frequently give indications very similar to those caused by drum malfunction. From that portion of the program being performed and the general condition of the indicators, the logical section of the machine at fault can usually be determined.

If the fault has been determined to be within the RM08 Serial Drum, but cannot be localized to a specific logic function, perform the diagnostic program procedure. When the location of a fault has been narrowed to a logic element, continue troubleshooting to locate the defective module or component by means of signal tracing. If the fault is intermittent, a form of aggravation test should be employed to locate the source of the fault.

- 6.2.1.1 <u>Diagnostic Program</u> Refer to program number MAINDEC-08-05AA-D from the Digital Program Library.
- 6.2.1.2 <u>Signal Tracing</u> If the fault has been located within a functional logic element, program the equipment to repeat some operation in which all functions of that element are utilized. Use the oscilloscope to trace a signal flow through the suspect logic element. Oscilloscope sweep may be synchronized by control signals or clock pulses available at individual module terminals. Trace the signal from the output back to its origin.
- 6.2.1.3 Aggravation Tests Intermittent failures caused by poor wiring connections can often be revealed by vibrating the modules while running a repetitive test cycle. Often, wiping the handle of a screwdriver across the back of a suspected row of modules is a useful technique. By repeatedly starting the equipment and vibrating fewer and fewer modules, the malfunction can be localized to within one or two modules. After isolating the malfunction in this manner, check the seating of the modules in the connector, check the module connector for wear or misalignment, and check the module wiring for cold solder joints or wiring kinks.

6.2.2 Circuit Troubleshooting

Where downtime must be kept at a minimum, it is suggested that a provisioning parts program be adopted to maintain one spare of each module type (Table 6-2) which can be inserted when system troubleshooting procedures have located the fault to a particular component.

Bench troubleshooting procedures can be performed to correct the defective components. Where downtime is not critical, the spare parts list can be reduced and signal tracing techniques can be utilized to troubleshoot modules within the equipment. This practice involves module removal by means of a Type 1960 System Module Puller, insertion of a Type 1954 System Module Extender into the logic rack, insertion of the suspect module in the module extender, and osiclloscope signal tracing of the module with the equipment energized and operating.

Table 6-2 Spare Module List

Module No.	Name
1213	Flip-Flop
1304	Delay (One Shot)
1410	Pulse Generator
1537	Drum Sense Amplifier
4102	Inverter
4106	Inverter
4112-47	Negative Diode NOR
4113	Negative Diode NOR
4114-74	Negative Diode NOR
4115–17	Positive Diode NOR
4127	Capacitor–Diode Gate
4141-R	Negative AND-NOR Gates
4215-X	Complementing Flip-Flops
4216	Shift Register
4217	Complementing Flip-Flops
4220-377	Buffer Register
4222-77	Counter Flip-Flops
4225	Counter Flip-Flops
4301	Delay (One Shot)
4303	Integrating Single Shot
4401	Variable Clock
4529	Drum Writer
4530	Drum X Select
4531	Drum Y Select
4604	Pulse Amplifier
4605	Pulse Amplifier
4606	Pulse Amplifier
6102-145	Inverter
6106–17	Inverter

Table 6-2 (cont.)
Spare Module List

Module No.	Name
6110	Negative Diode NOR
6113	Positive Diode NOR
6115-12	Positive Diode NOR
R107	Inverter

Static and dynamic circuit troubleshooting procedures may be performed at a bench. Visually inspect the module on both the component side and the printed-wiring side to check for short circuits in the etched wiring and for damaged components. If this inspection fails to reveal the cause of trouble or confirm a fault condition observed, use the multimeter to measure resistances.

CAUTION

- a. Do not use the lowest or highest resistance ranges of the multimeter when checking semiconductor devices. The X10 range is suggested. Failure to heed this warning may result in damage to components.
- b. Do not attempt to measure resistance of any clock head. The voltage applied to the test probes is sufficient to erase information from the drum surface.

Measure the forward and reverse resistances of diodes. Diodes should measure approximately 20 ohms forward and more than 1000 ohms reverse. If readings in each direction are the same and no parallel paths exist, replace the diodes.

Measure the emitter-collector and emitter-base resistance of transistors. Most catastrophic failures are due to short circuits between the collector and the emitter or due to an open circuit in the base-emitter path. A good transistor indicates an open circuit in both directions between collector and emitter. Normally 50 to 100 ohms exist between the emitter and the base or between the collector and the base in the forward direction, and open-circuit conditions exist in the reverse directions. To determine forward and reverse directions, a transistor can be considered as two diodes connected back-to-back.

In this analogy PNP transistors are considered to have both cathodes connected together to form the base and both the emitter and collector assume the function of an anode. In NPN transistors, the base is assumed to be a common-anode connection and both the emitter and collector are assumed to be the cathode. Multimeter polarity must be checked before measuring resistances, since many meters (including the Triplett 630) apply a positive voltage to the common lead when in the resistance mode. Note that although incorrect resistance readings are a sure indication that a transistor is defective, correct readings give no guarantee that the transistor is functioning properly. More reliable indication of diode or transistor malfunction is obtained through the use of one of the many inexpensive in-circuit testers commercially available.

Damage or cold-solder connections can also be located using the multimeter. Set the multimeter to the lowest resistance range and connect it across the suspected connection. Poke at the wires or components around the connection, or alternately rap the module lightly on a wooden surface, and observe the multimeter for open-circuit indications.

Often the response time of the multimeter is too slow to detect the rapid transients produced by intermittent connections. Current interruptions of very short duration, caused by an intermittent connection, can be detected by connecting a 1.5V flashlight battery in series with a 1500-ohm resistor across the suspected connection. Observe the voltage across the 1500-ohm resistor with an oscilloscope while probing the connection.

Dynamic bench testing of modules can be performed through the use of special equipment. A Type 922 Test Power Cable and either a Type 722 or Type 756 Power Supply can be used to energize a system module. These supplies provide both the +10 Vdc and -15 Vdc operating supplies for the module as well as ground and -3V sources which may be used as signal inputs. The signal inputs can be connected to any terminal normally supplied by logic level by means of eyelets provided on a Jones plug on the power cable. Type 911 Patch Cords may be used to make these connections on the Jones plug. In this manner logic operations and voltage measurements can be made. When using the Type 765 Bench Power Supply, marginal checks of an individual module can also be obtained.

6.2.3 Repair

In all soldering and unsoldering operations in the repair and replacement of parts, avoid placement of excessive solder or flux on adjacent parts or service lines. When soldering semiconductor devices (transistors, crystal diodes, and metallic rectifiers) which may be damaged by heat, the special precautions that follow should be taken.

a. Use a heat sink, such as a pair of pliers, to grip the lead between the device and the joint being soldered.

- b. Use a 6V soldering iron with an isolation transformer. Use the smallest soldering iron adequate for the work.
- c. Perform the soldering operation in the shortest possible time to prevent damage to the component and delamination of the module etched wiring.

When any part of the equipment is removed for repair and replacement, make sure that all leads or wires which are unsoldered, or otherwise disconnected, are legibly tagged or marked for identification with their respective terminals.

6.2.4 Head Pad Replacement

This replacement should be performed only by qualified personnel. To replace the head pads, the tools that are listed below are required.

- a. Surface plate (at least 3 ft by 2 ft)
- b. Two 2-inch machinists' parallels
- c. Aligning pin, VRC (Vermont Research Corp.) part no. 59P7
- d. Steel Scale, 1/32-inch calibrations
- e. Height comparator with 0.000, 050 inch calibration (or finer), with less than 5 gram contact pressure. The "Electroprobe" manufactured by Federal Products, Providence, R.I., is suggested.
 - f. Adjustable height gage, 3- to 4-in. micrometer caliper

Replacement of the head pad must be done with the head mounting bar removed from the drum. This is done by removing the four socket head cap screws at the ends of the bar, disconnecting the matrix wiring, and setting the head mounting bar on the two parallels on the surface plate. Place the bar with the bearing surface of the pads upward and the stop adjusting screws accessible at the edge of the surface plate.

Remove the head pad by removing screws at the pad and those holding the leads with a strain relief and the associated connector. Insert the new pad, bending the leads gently. Replace all screws. Check polarization of connector locating pins (which also serve as mounting screws) to ensure proper mating with the other half. Before tightening head pad mounting screws, insert the aligning pin through the corresponding hole in the bar and up into the aligning hole in the loose pad.

Insert aligning pin into the pad carefully, making sure that no leads are caught at the pin hole. With the pin in place, scale the distance from each end of the pad to the reed mount and adjust the parallel within 1/64 inch. Tighten pad mounting screws and recheck parallelism. Remove the aligning pin and proceed to height adjustment.

Using housing flat-to-drum dimensions and the required drop allowance, measure the thickness of the bar and parallels in use and calculate the height setting for the height gage as follows.

Housing-to-Drum Dimension - Drop Allowance = Required Bar-to-Head Dimension Required Bar-to-Head Pad Dimension + Parallel Thickness + Bar Thickness = Height Gate Setting

Set the height gate to size using the micrometer caliper; then use the height gage to set the comparator to zero or center range. Rotate the actuator link and allow the head pad to move into actuated position. Using a hexagonal wrench in the corresponding stop screw, lower the pad being adjusted until the height comparator reads approximately zero at the center of the pad. Check elevation of the entire pad. Using the two differential pad leveling screws between the read mount and bar, and the stop screw for overall elevation, set the pad level within 0.0001 in. (leading to the trailing edge) and 0.0002 in. (end to end).

Replace the bar on the drum housing. Replace all matrix boards and wiring. Monitor the output signal from the replaced head pad (as described previously for head pad adjustment) while letting this pad approach the recording surface for the first time. As the stop screw is moved out, allowing the actuator to move the pad into "flying position," compare output levels on heads 1 and 8 (top and bottom) in the pad. Balance these levels with $\pm 10\%$ with the differential screw adjustment at partial output levels; then move the stop screw out father until the "peaking" process (described under Head Adjustment) is complete.

6.2.5 Validation Test

Following the replacement of any electrical component of the equipment, a test should be performed to assure the correction of the fault condition and to make any adjustments of timing or signal levels caused by the replacement. This test should be taken from the preventive maintenance procedure most applicable to the portion of the system in which the error was found. For example, if a filter capacitor was replaced in the proper supply, the ripple check for that power supply should be repeated as specified under Power Supply Checks. If repairs or replacements are made in an area which is not checked during preventive maintenance, the diagnostic program should be run or an appropriate operational test should be devised. For example, if a flip-flop is repaired or replaced, the register or control function performed by the flip-flop should be checked in entirety by manually setting and clearing, by programmed exercise of the function, or by repeating the diagnostic program.

6.2.6 Log Entry

Corrective maintenance activities are not completed until they are recorded in the maintenance log. Record all data indicating the symptoms given by the fault, the method of fault detection, the component at fault, and any comments which would be helpful in maintaining the equipment in the future.

CHAPTER 7 ENGINEERING DRAWINGS

This chapter contains reduced copies of the DEC engineering prints on the Type RM08 Serial Drum. Only those drawings are included which are essential and are not available in the referenced documents that are pertinent to this system are included.

7.1 DRAWING NUMBERS

DEC engineering drawing numbers contain five groups of information separated by hyphens. For example, drawing number BS-D-RM08-0-4 includes the information that follows.

BS - type of drawing

D - original drawing size

RM08 - equipment type

manufacturing series of the equipment

4 - drawing number within the series

The drawing types are listed below:

BS, block schematic or logic diagram

CD, cable diagram

CL, cable list

CS, circuit schematic diagram

FD, flow diagram

ID, interconnection diagram

MA, mechanical assembly diagram

ML, module location diagram

PW, power wiring diagram

RS, replacement schematic diagram

SD, system diagram

TD, timing diagram

TFD, timing and flow diagram

TSL, terminal strip location diagram

UML, utilization module list

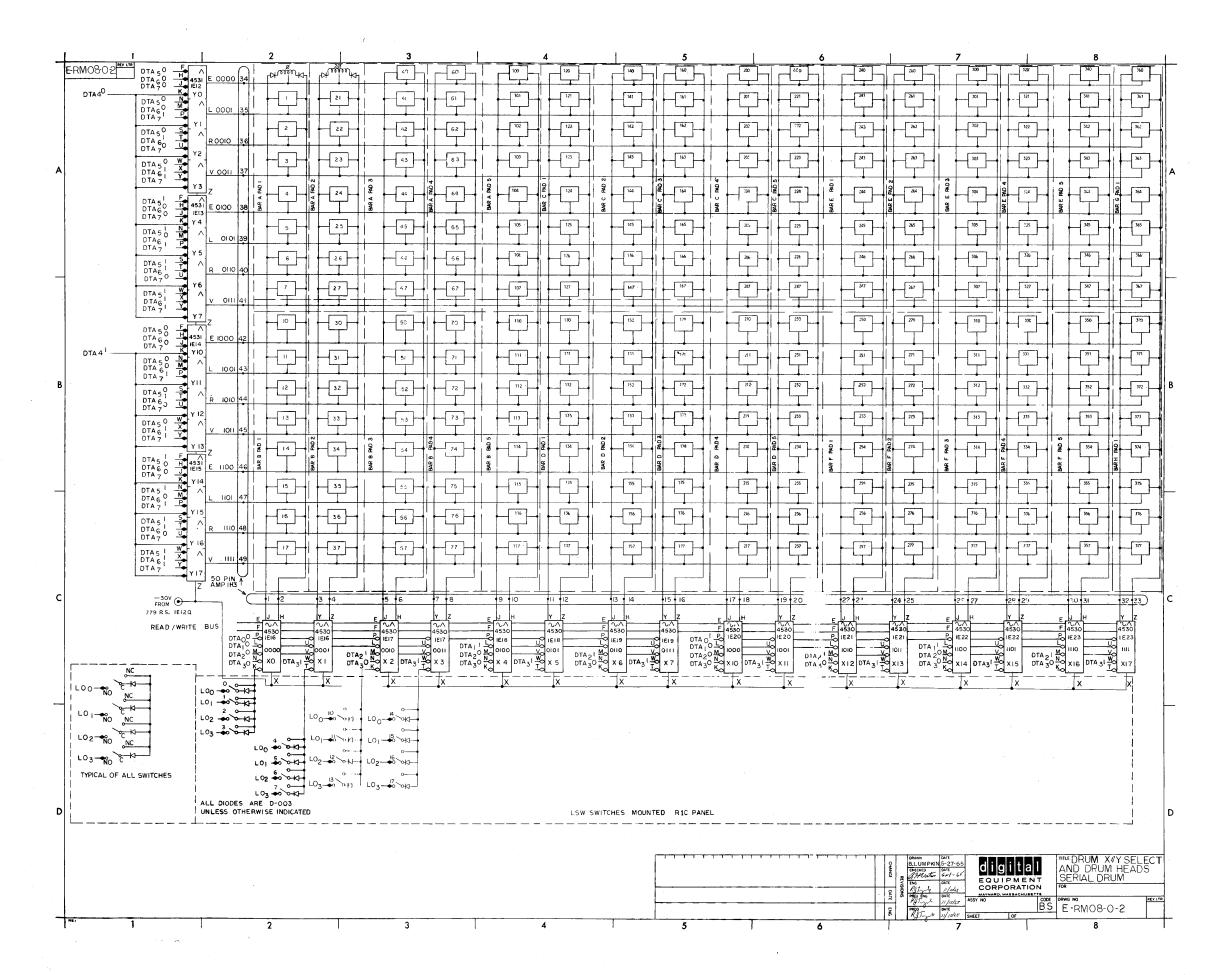
WD, wiring diagram

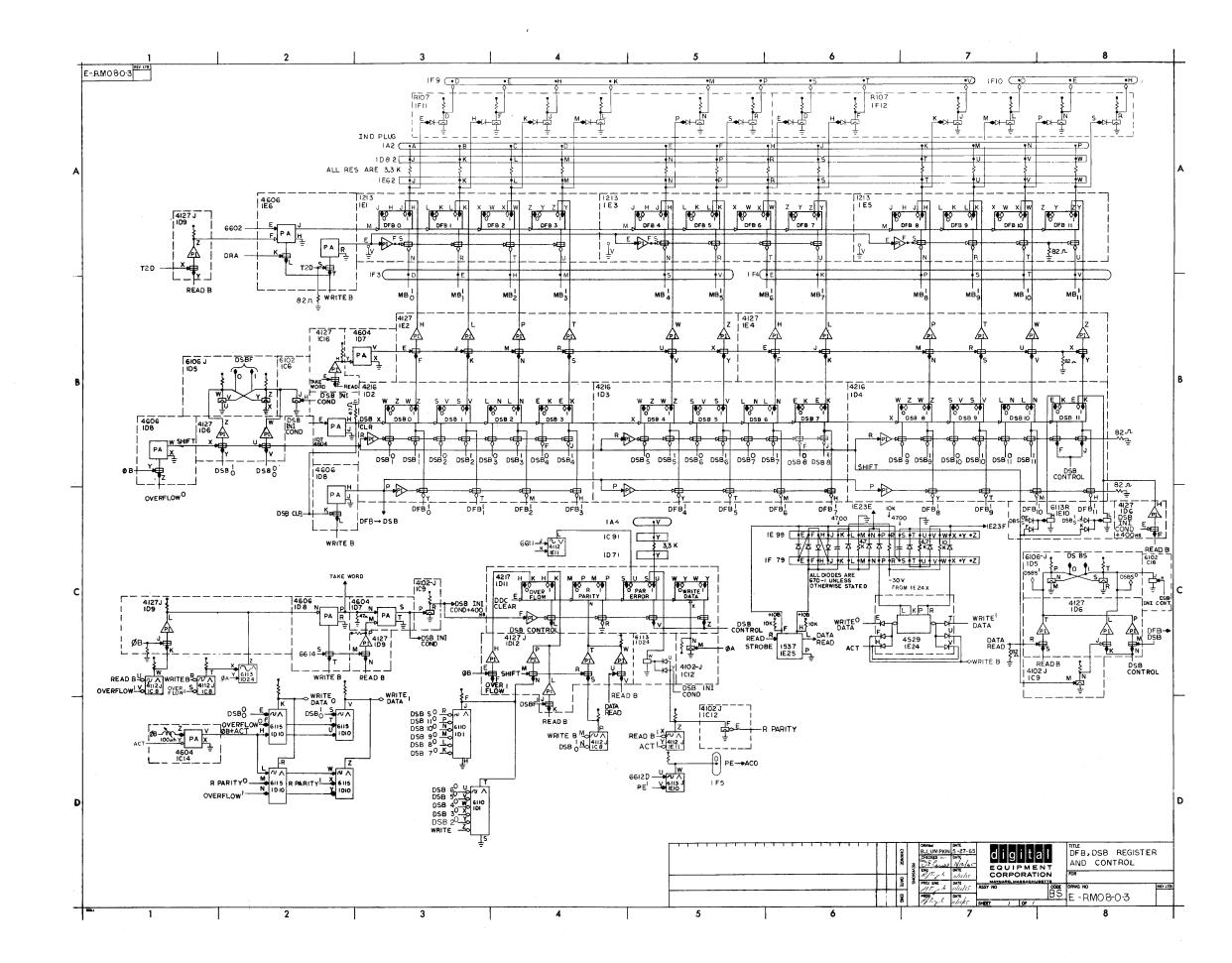
WL, wiring list

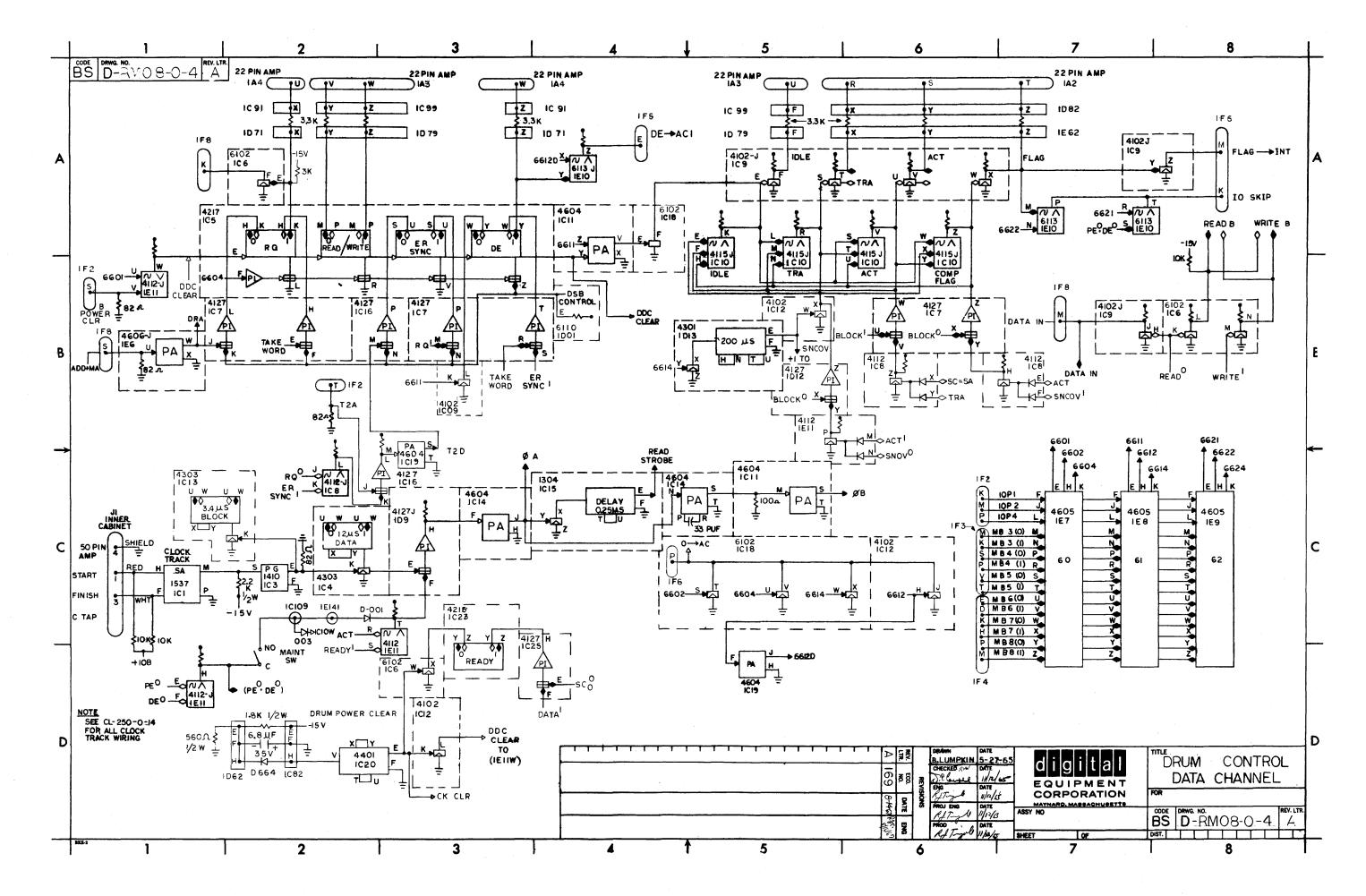
WS, wiring sheet

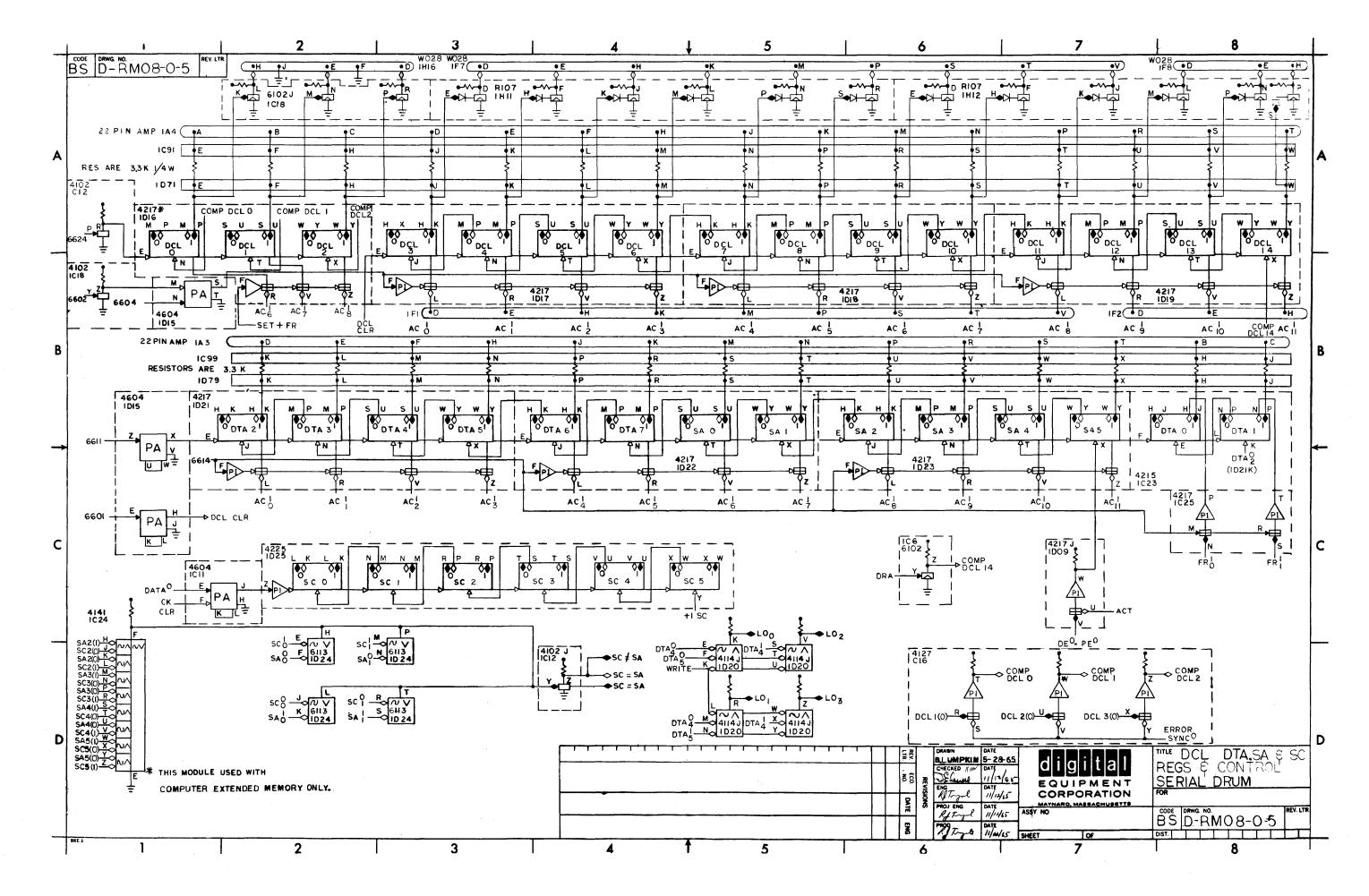
7.2 CIRCUIT SYMBOLS

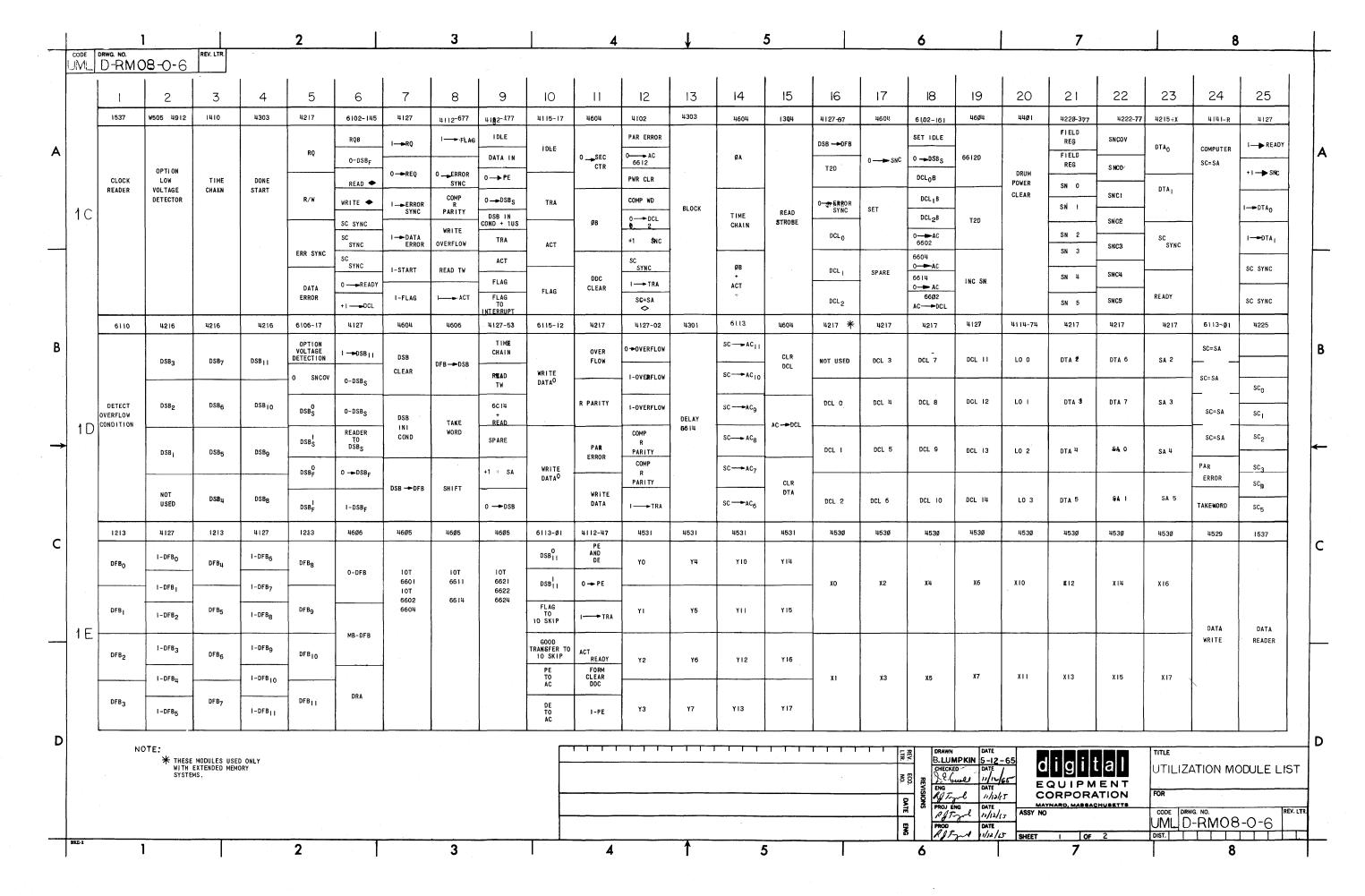
The block schematics of DEC equipment are multipurpose drawings that combine signal flow, logical function, circuit type and physical location, wiring, and other pertinent information. Individual circuits are shown in block, or semi-block form, with special symbols that define the circuit operation. These symbols are defined in the FLIP CHIP Modules Catalog and the Systems Module Catalog.

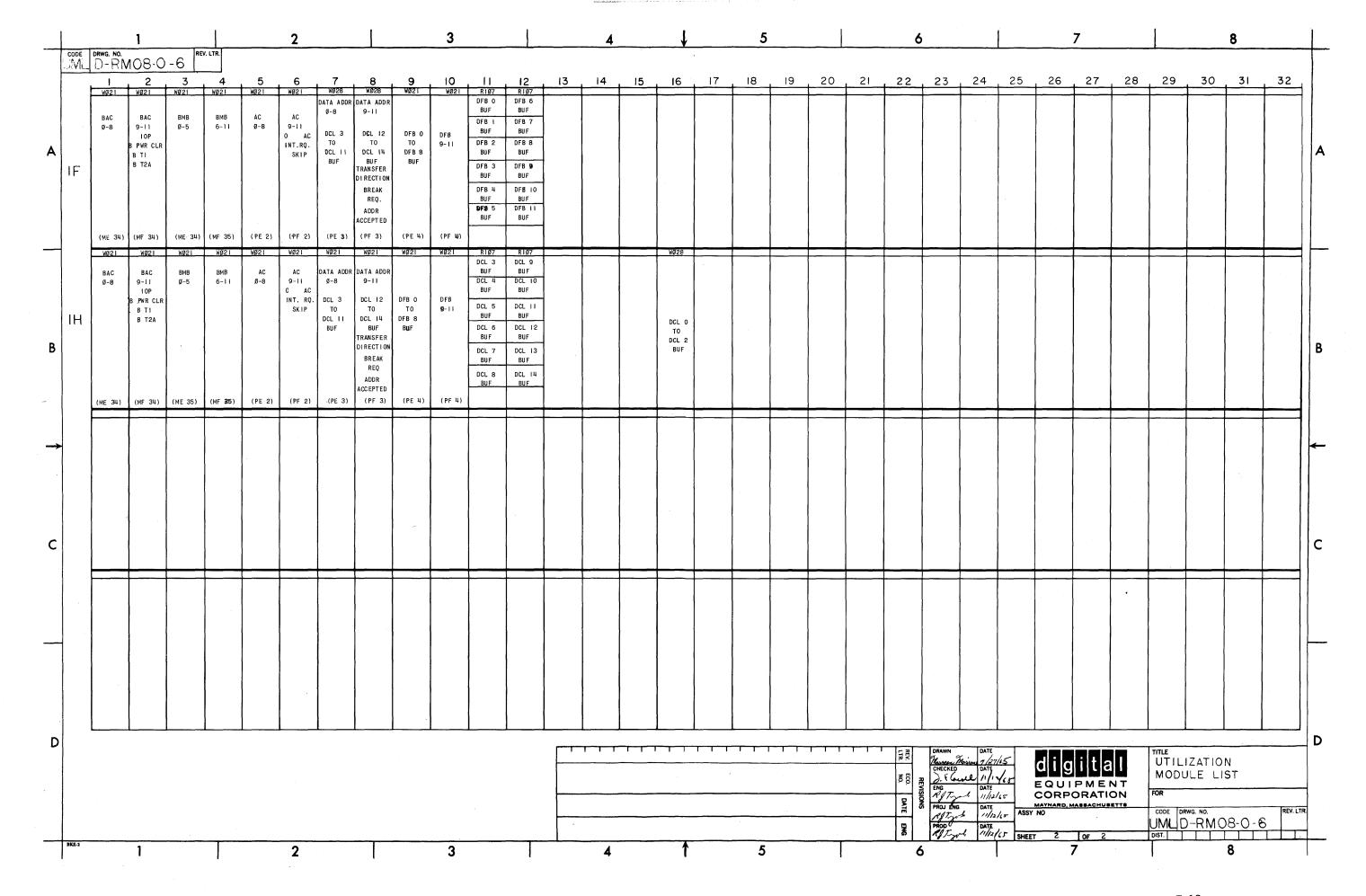


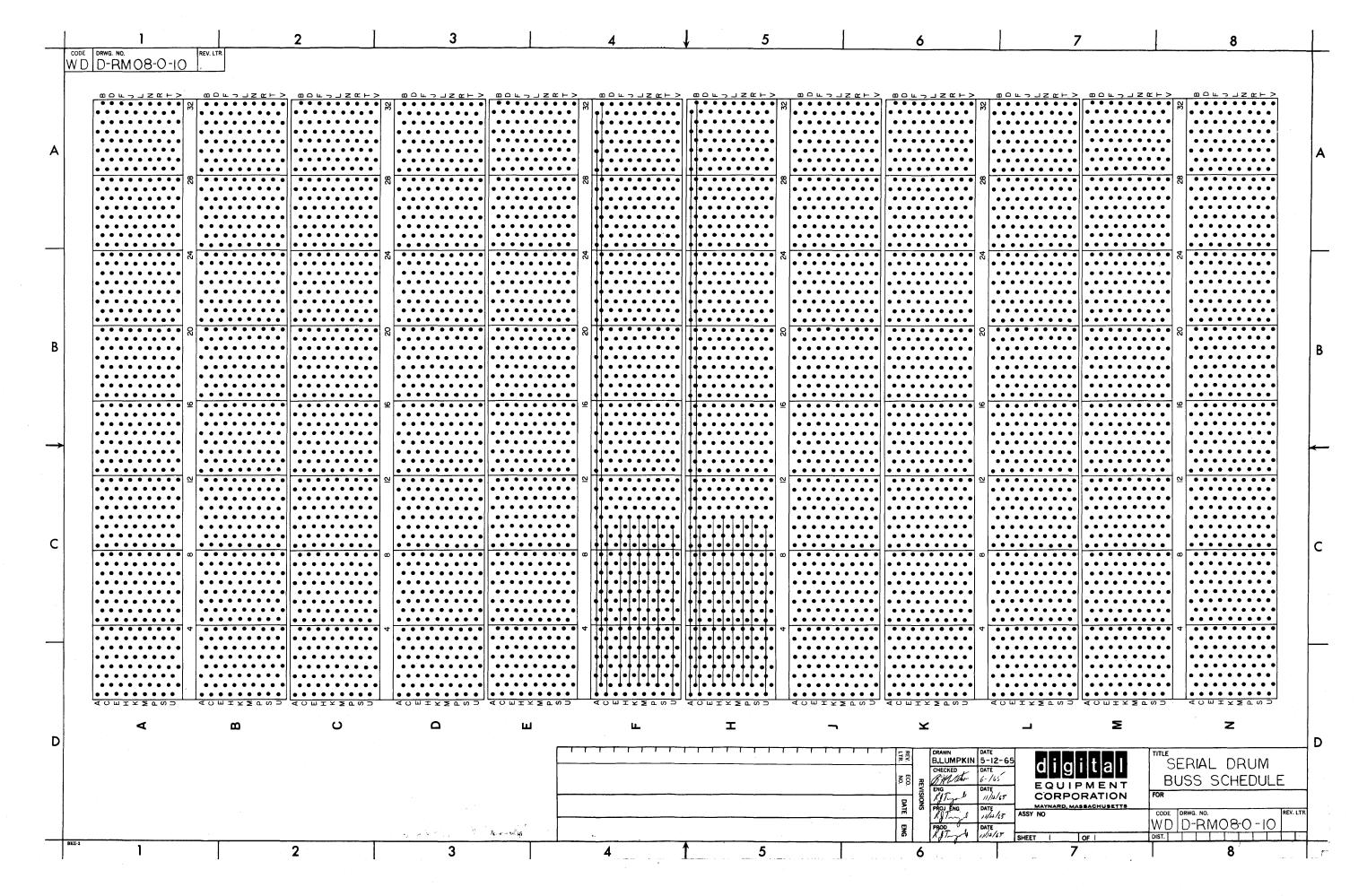


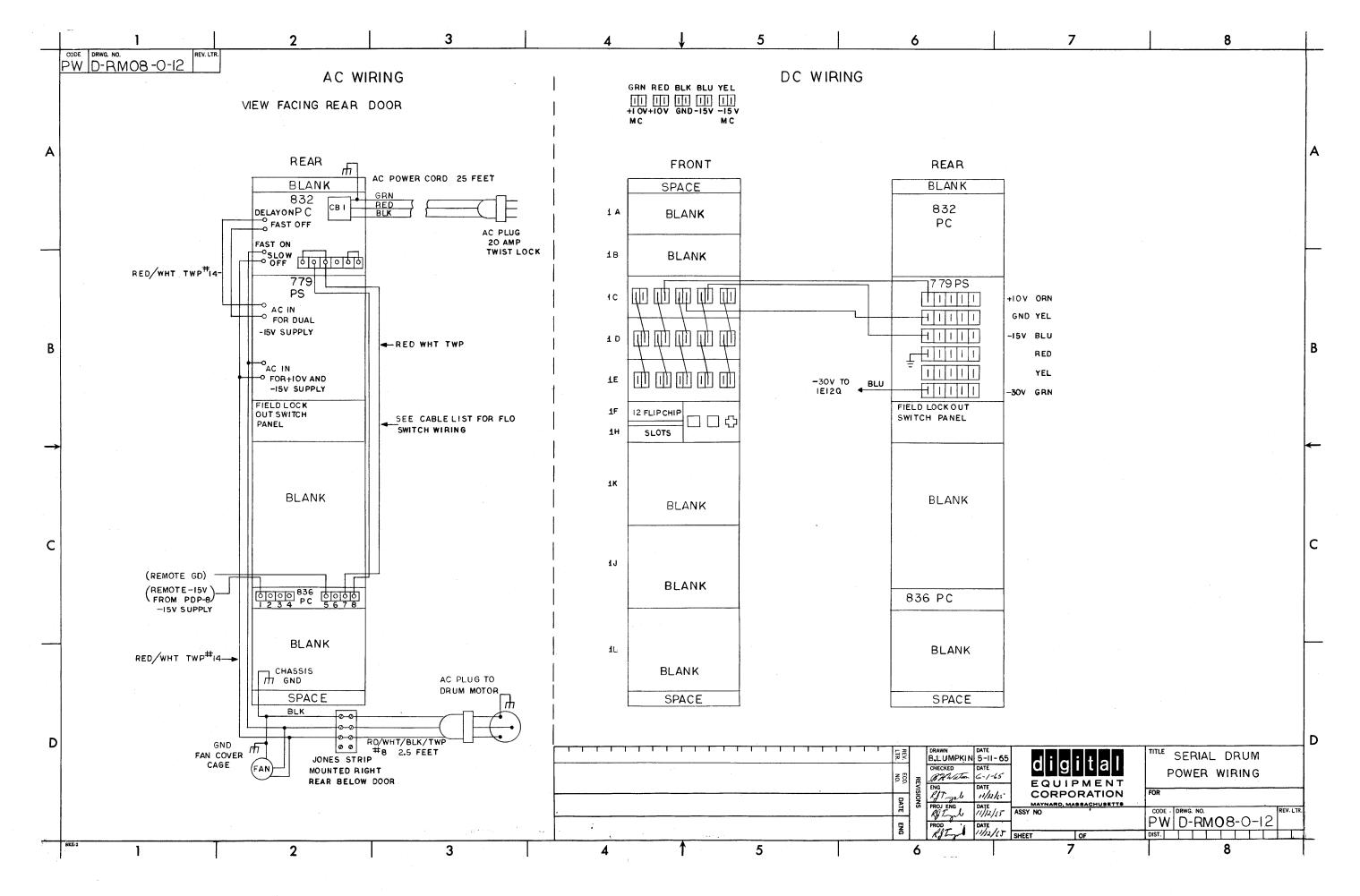


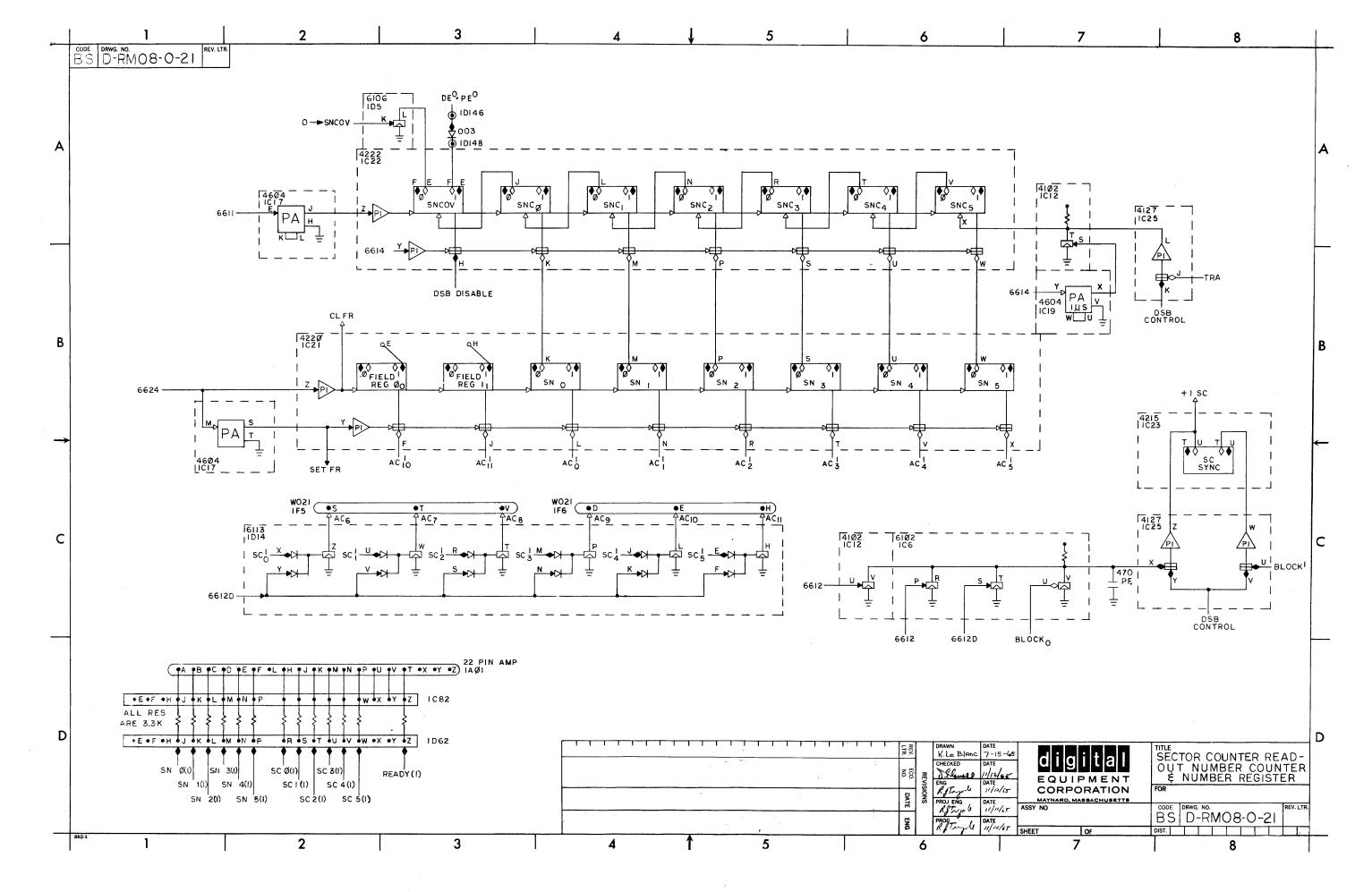


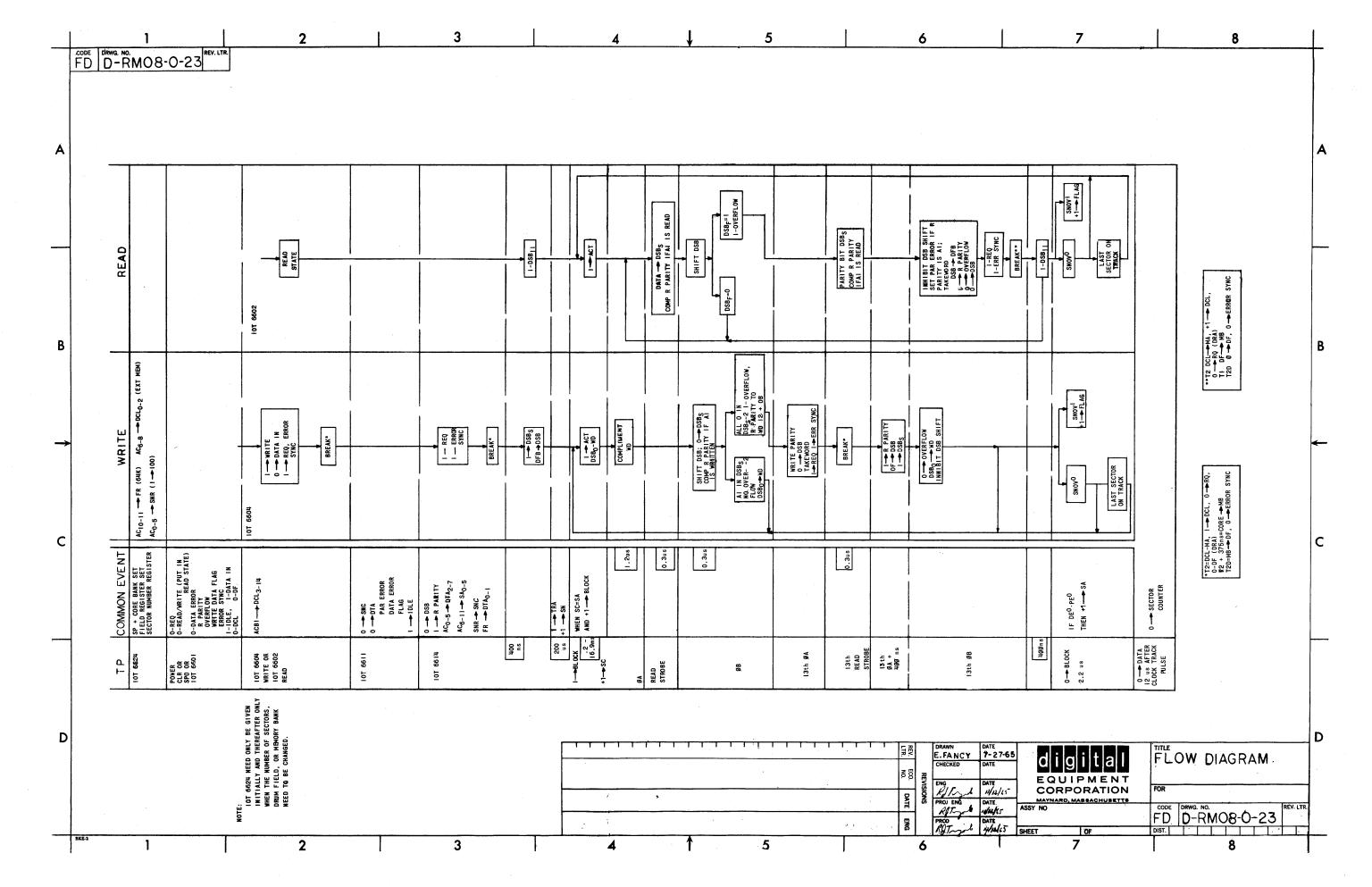












JACK X	PLUG		LOCATION, LE	OUTE	DUTE				
FEMALE X	MALE		1J3 OF	PLUG P	ANEL				
COLOR	PIN PIN		NAME	COLOR		PIN .	PIN	NAME	
RED TWP	1E16J	1	X0	RED ?	TWD	1E22J	26	X14	
GRN	H	2	x0	GRN		н	27	X14	
RED 7 TWP	Y	3	X1	RED	TWP	Y	28	X15	
GRN	1E16Z	4	X1	GRN		1E22Z	29	X15	
RED 7 TWP	1 <u>E</u> 17J	5	X2	RED?	TWP	1E23J	30	X16	
GRN	Н	6	X2	GRN		H	31	X16	
RED TWP	Y	7	х3	RED ~	TWP	Y	32	x 1 7	
GRN	1E17Z	8	х3	GRN		1E23Z	33	x17	
RED TWP	1E18J	9	X4	BLK		1E12E	34	Y0	
GRN J	H	10	X4	 		L	35	Yl	
RED TWP	Y	11	X5			♥ R	36	Y2	
GRN J	1E18Z	12	X5			1E12V	37	У3	
RED ~ TWP	1E19J	13	X6			1E13E	38	¥4	
GRN	H	14	X7			L	39	¥5	
RED TWP	Y	15	х7			▼ R	40	Y6	
GRN	1E19Z	16	X7			1E13V	41	¥7	
RED TWP	1E20J	17	X10			1E14E	42	Y10	
GRN	Ťн	18	x10			L L	43	Y11	
RED TWP	▼ Y	19	x11			r	44	Y12	
GRN	1E2OZ	20	Xll			1E14V	45	Y13	
		21				1E15E	46	Y14	
RED TWP	1E21J	22	X12			↑ L	47	Y15	
GRN	H	23	X12			R	48	Y16	
RED 7 TWP	YY	24	X13			1E15V	49	Y17	
GRN	1E21Z	25	x13	BLK		GND	50	GND	
REV. LTR. ECO. N	O. DATE E	NG.			5C	PIN A	MPH	IENOL	
			digit	all	TITLE				
			EQUIPME	NT	'''	SERIAL D			
			CORPORAT			R/W HEAD		CT	
			MAYNARD, MASSACH	USETTS		DRUM :	OT DE		
			DRAWN FOR						
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JACK	PLU	JG X	LOCA	LOCATION, LENGTH, ROUTE							
FEMALE	MA	LE X	Jl	J1 ON DRUM TO LOGIC							
COLOR	PIN	PIN	1 1	NAME	COL	OR		PIN	PIN	NA	ME
RED	1C1H	1	START	.)	RED		10	ClH	26	START	
BLACK	Å	2	CT	CLOCK	BLACE	ζ	4		27	CT	CLOCK
GREEN	F	3	FIN.	#1	GREEN	J		F	28	FIN.	#7
SHIELD	G1	_{ND} 4	GND		SHIE	D_		GND	29	GND	
RED	Н	5	START		RED			H	30	START	
BLACK		6	CT	CLOCK	BLACE	ζ			31	CT	CLOCK
GREEN	F	7	FIN.	#2	GREEL	1	,	F	32	FIN.	#8
SHIELD	Gì	4D 8	GND		SHIEI	D	1	ClGND	33	GND	
RED	Н	9	START	(1)					34		
BLACK		10	СТ	CLOCK	NOTE				35		
GREEN	F	11	FIN.	#3		RPIN	CON	NECTION	36		
SHIELD	Gl	_{1D} 12	GND					USE TRIPI	_E 37		
RED	Н	13			CONDU	JCTOR	SHI	ELDED WIF	E38		
BLACK		14	CT.	CLOCK				OUTPUTS	39		
GREEN	▼ F	15		#4	AND 1	INITI	ALLY	USE HEAD	40		
SHIELD	1ClGN	10 16	+) "	 		†	OUTPUT.	41		
		17			1			ERS AS	42		
RED	1C1H	18	START	.)	1			END MUST	43		
BLACK	A	19	+	CLOCK	1			TED WHILE	44		
GREEN	F	20		#5	WIRI				45		
SHIELD	G1	ND 21	,						46		
RED	H	22		5					47		
BLACK		23	CT	CLOCK					48		
GREEN	F	24		\ +6					49		
SHIELD	1C1GN	_{ID} 25							50		
REV. LCO A		ENG.	IGENE				<u> </u>	DINI AR	AD	LICAL	
LTR. ECO. IV	O. DATE	Liva.	di	alilt	all	יכ		PIN AN	VIP	HEIN	OL
						TITLE		SERIAL D	RUM	RM08	
		 		JIPME PORAT				CLOCK RA	CK I	PLUG	
-	_	 		D, MASSACH							
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			M. Mar	riamo 5/	13/65					·	
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JACK	PLU	G X	LOCATION, LENGTH, ROUTE						
FEMALE	MALE X		J3 PLUG PANEL TO J2 DRUM CABLE		16 "	16" INSIDE DIMENSION			
COLOR	PIN MALE	PIN MALE	NAME	COL	OR	PIN	PIN	NAM	IE
RED TWD	1	1	X0	RED ?	TWP	26	26	X14	
GRN	2	2	x0	GRN	IWF	27	27	X14	
RED 7 TWP	3	3	хl	RED)	TWP	28	28	X15	
GRN	4	4	x1	GRN		29	29	X15	
RED TWP	5	5	X2	RED	TWP	30	30	X16	
GRN	6	6	X2	GRN		31	31	X16	
RED TWP	7	7	х3	RED	TWP	32	32	x17	
GRN	8	8	х3	GRN		33	33	X17	
RED TWP	9	9	x4	BLK		34	34	Y0	
GRN	10	10	X4	A		35	35	Yl	
RED 7 TWP	11	11	X5			36	36	¥2	
GRN	12	12	X5			37	37	Y3	
RED TWP	13	13	х6			38	38	Y4	
GRN	14	14	X6			39	39	¥5	
RED ? TWP	15	15	X7			40	40	¥6	
GRN	16	16	X7			41	41	Y 7	
RED TWP	17	17	x1 0			42	42	Y10	
GRN	18	18	Y10			43	43	Y11	
RED TWP	19	19	X11			44	44	Y12	
GRN	20	20	X11			45	45	Y13	
WHT	21	21	SPARE			46	46	Y14	
RED 7WP	22	22	X12			47	47	Y15	
GRN	23	23	X12			48	48	Y16	
RED?	24	24	X13	•		49	49	Y1 7	
GRN TWP	25	25	X13	BLK		50	50	GND	,
REV. ECO. N	O. DATE	ENG.			50	O PIN A	MPI	HFNC)
			dialit	all	TITLE				
			EQUIPMENT			LE SERIAL DRUM RM08			
			CORPORAT						
			MAYNARD, MASSACH	USETTS	}				
			RAWN	FOR					
	M. Mariano 5/13/ CHECKED		13/65	CODE DRWG. NO.			REV.		
		Ci	HEUKED		1				REV.
		El	NG. CL A-RM08-0-17						
		DE	ROD.	SHEET 1 OF 1					
					DIST.				

COLOR	NAME	PIN	PIN	REMARKS	
BLUE	PE ^O →DE ^O	1E11H	MAINT SW COMMON		
BLUE	PE ^O • DE ^O	10090	MAINT SW NORM OPEN		
WHITE	ro ₀	1D20K	SW 0 NORM OPEN		
WHITE	Lo ¹	1D20R	SW 1 NORM OPEN		
WHITE	Lo ²	1D20V	SW 2 NORM OPEN		
WHITE	LO3	1D20Z	SW 3 NORM OPEN		
			•		
RED	LOF0	NORM CLOSED BUS SW 0,SW 1,SW	, SW3		
RED	LOF1	NORM CLOSED BUS SW4,SW5,SW6,S	3W7	·	
RED	LOF2	NORM CLOSED BUS SW 8 , SW 9 , SW			
RED	LOF3	NORM CLOSED BUS SW1 2, SW13, SV	NORM CLOSED BUS SW1 2, SW13, SW14, SW15		
WHITE	LO0	NORM OPEN BUS SW 0-SW4-SW8	-SW12		
WHITE	LOl	NORM OPEN BUS SW1-SW5-SW9	SW13		
WHITE	LO2	NORM OPEN BUS SW2-SW6-SW10-	SW14		
WHITE	LO3	NORM OPEN BUS SW3-SW7-SW11	-sw15		
NOTE:	D003 DIODES W	ILI BE MOUNTED ONALL	SWITCHES, BAR EN	TO COMMON,	
	OTHER END TO	NORM CLOSE POSITION.			
	LOF2	lel7K	SW11/NC		
	LOF3	lel7T	sw15/nc		
	LOF0	1E16K	sw3/nc	·	
	LOF1	1E16T	sw7/NC		
NOTE:	REFERENCE BS-	E-250-0-6.			
REV. ECO. N	IO. DATE ENG.		GENERAL WI	RING SHEET	
A 107	12/1/66 RIT	digital	TITLE FIELD LOCA		
	V	EQUIPMENT	WIRING	KOUT PANEL	
		CORPORATION MAYNARD, MASSACHUSETTS	SERIAL DRU	JM RM08	
		DRAWN			
		M. Mariano 5/13/65			
		CHECKED	CODE DRWG. NO.	REV.	
		ENG.	WS A-RM08-0-1	8 A	
		PROD	SHEET 1 OF	1	
		PROD.	DIST.		

JACK	PLUG [x]	LOCATION, LENGTH, F	OUTE		
FEMALE X	MALE [1AØ4			
COLOR	PIN	PIN	NAME		REMARKS	
W/BLK (X)	1C91E	Α	DCL 0			
W/BRN (Z)	F	В	1			
W/RED (R)	н	С	2			
W/ORN (0)	J	D	3			
W/YEL (Y)	К	E	4			_
W/GRN(N)	L	F	5			
W/BLU (B)	М	Н	6			
W/VIO (V)	N	J	7			V
W/GRY (G)	P	K	8			
WHT (W)		L				
W/BLK (X)	1C91R	М	DCL 9			
W/BRN (Z)	s	N	10			
W/RED (R)	т	Р	11			
W/ORN (O)	υ	R	12			
W/YEL (Y)	v	S	13			
W/GRN(N)	w	Т	14			
W/BLU (B)	1C91X	U	RQ			
W/VIO (V)	1C91Y	٧	PAR ERR			
W/GRY (G)	1C91Z	W	DE			***************************************
WHT (W)		Χ				
		Y				
		Z				
DRAWN	The state of the s			22	PIN AMPHEN	OL
CHECKED 2	ariano 8/5/6!	1		TITLE	,	
ENG RAT	Jell11 11/12/1	/ 2 2 	EQUIPMENT CORPORATION MAYNARD, MASSACHUSETTS	D	ORUM CORE LOCATION INDICATOR CABLE	
			APP'V			
			REV. I	DWG NO	-RM08-0-24	REV. LTR.
			LTR.	SHEET	OF	CODE CL

JACK	PLUG [x	LOCATION, LENG	TH, R	OUTE		
FEMALE X	MALE [lAØ ₁				
COLOR	PIN	PIN	NAME			REMARKS	
W/BLK (X)	1С82Ј	Α	sn o				
W/BRN (Z)	K	В	1				
W/RED (R)	L	С	2				
W/ORN (O)	М	D	3				
W/YEL (Y)	N	E	4				
W/GRN(N)	P	F	- 5				
W/BLU (B)	R	Н	sc ø				
W/VIO (V)	S	J	sc 1				
W/GRY (G)	Т	К	SC 2				
WHT (W)		L					
W/BLK (X)	1C82U	M	sc 3				
W/BRN (Z)	v	N	4				
W/RED (R)	w	Р	5				
W/ORN (O)		R		_			
W/YEL (Y)		S					
W/GRN(N)	1C82Z	T	READY 1				
W/BLU (B)		U					
W/VIO (V)		٧					
W/GRY (G)		W					
WHT (W)		x					
		Υ					
		Z					-
DRAWN				IH	22	PIN AMPHEN	OL
Maureen Marian o 8/5/65 CHECKED			digital TITLE				
J & Carroll // 1/63			EQUIPMENT CORPORATION			DRUM SECTOR COUNTER	
ENG P	1. 5 11 - 14:	-	MAYNARD, MASSACHUS			INDICATOR CABLE	
				AP			
				APP'V			
				ᇛᄪ	DWG NO)	REV. LTR.
				ECO. REV.		A-RM08-0-25	
				NO. LTR.	SHEET	OF	CODE
					L		1 611

JACK	PLUG [x	LOCATION, LE		OUTE		
FEMALE X	MALE]	LAØ2			
COLOR	PIN	PIN	N.	AME		REMARKS	
W/BLK (X)	1D82J	Α	DFB 0				
W/BRN (Z)	K	В	1				
W/RED (R)	L	С	2				
W/ORN (O)	М	D	3				
W/YEL (Y)	N	E	4				
W/GRN(N)	P	F	5				
W/BLU (B)	R	Н	6				
W/VIO (V)	S	J	7				
W/GRY (G)	T	К	8				
WHT (W)		L					
W/BLK (X)	1D82U	М	DFB 9				
W/BRN (Z)	v	N	10)			
W/RED (R)	W	Р	11				
W/ORN (O)		R					
W/YEL (Y)		S					
W/GRN(N)		Т					-
W/BLU (B)		U					,
W/VIO (V)		V					
W/GRY (G)		W					
WHT (W)		Х		-			
		Υ					
		Z					
DRAWN	0/5/6	_ [digii	IAL	22	PIN AMPHEN	OL
	Maureen Mariano 8/5/65 CHECKED			al	TITLE		
	and which		EQUIPMENT CORPORATION MAYNARD, MASSACHUSETTS			DRUM FINAL BUFFER INDICATOR CABLE	
				APP'V			
				ď			
				ECO. REV.	DWG NO		REV. LTR.
				1	A-	-RM08-0-26	
				NO.	SHEET	OF	CODE CL

JACK	PLUG [x	LOCATION, LENGTH, R	OUTE
FEMALE X	MALE		1AØ3	
COLOR	PIN	PIN	NAME	REMARKS
W/BLK (X)		Α		
W/BRN (Z)	1С99Н	В	DTA 0	
W/RED (R)	1С99Т	С	DTA 1	
W/ORN (O)	1с99к	D	DTA 2	
W/YEL (Y)	1C99E	Ε	DTA 3	
W/GRN(N)	1C99M	F	DTA 4	
W/BLU (B)	1C99N	Н	DTA 5	
W/VIO (V)	1C99P	J	DTA 6	
W/GRY (G)	1C99R	K	DTA 7	
WHT (W)		L		
W/BLK (X)	1C99s	М	sa ø	
W/BRN (Z)	1С99Т	N	SA 1	
W/RED (R)	1C99U	Р	SA 2	
W/ORN (O)	1C99V	R	SA 3	
W/YEL (Y)	1C99W	S	SA 4	
W/GRN(N)	1C99X	T	SA 5	·
W/BLU (B)	1C99F	U	IDLE	
W/VIO (V)	1€99¥	٧	READ	
W/GRY (G)	1C99Z	W	WRITE	
WHT (W)		Х		
		Υ	-15V	
		Z	GND	
DRAWN	0.4-10			22 PIN AMPHENOL
Maureen Ma	ariano 8/5/6	I = I	digital	TITLE
ENC	acoexil	13/63	EQUIPMENT CORPORATION MAYNARD, MASSACHUSETTS	DRUM TRACK ADDRESS INDICATOR CABLE
			APP'V	
			REV. LTR	DWG NO REV.LTR. A-RM08-0-27
				SHEET OF CODE CL

